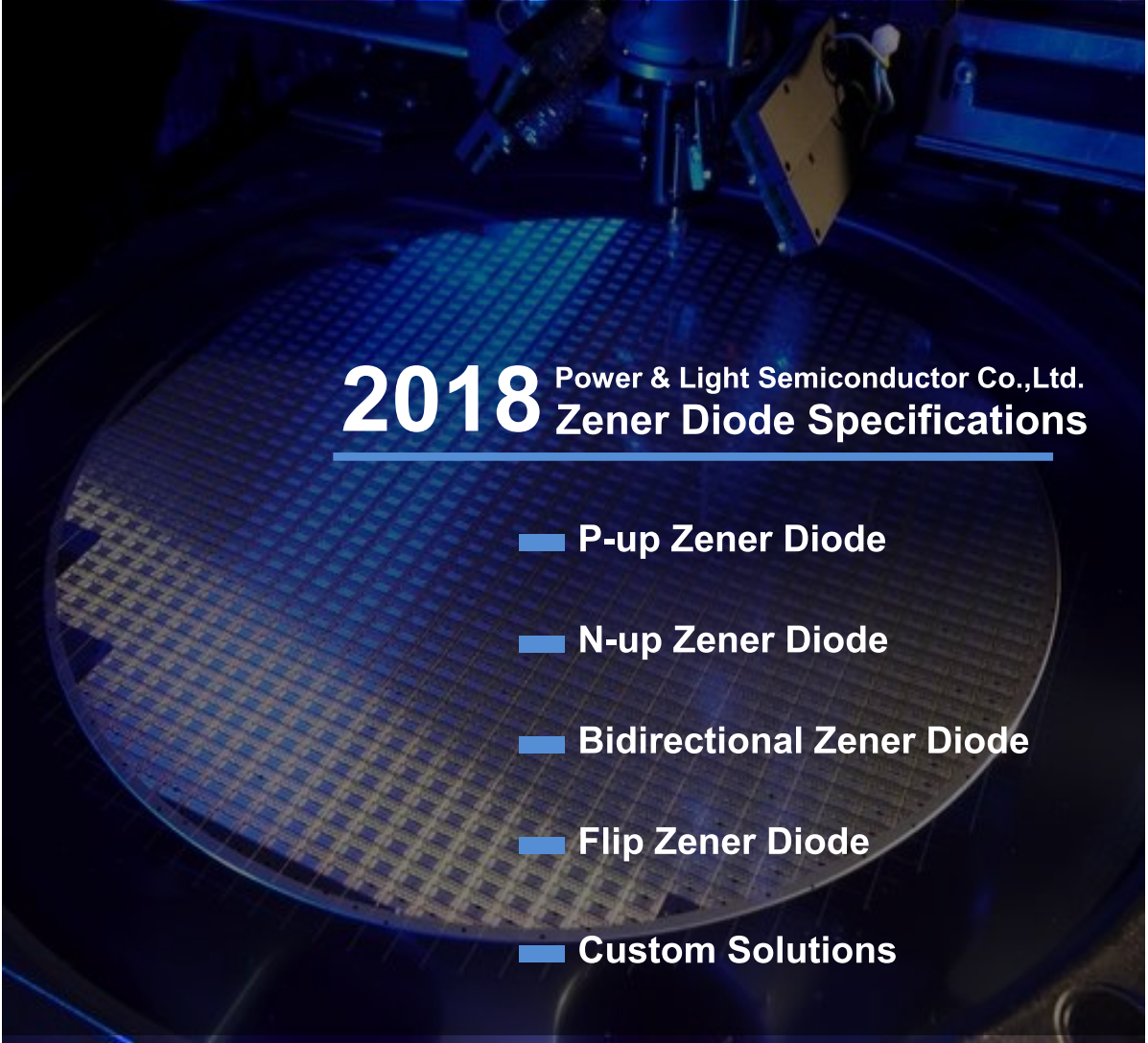




2018 Power & Light Semiconductor Co.,Ltd. Zener Diode Specifications

- P-up Zener Diode
- N-up Zener Diode
- Bidirectional Zener Diode
- Flip Zener Diode
- Custom Solutions

P&L SEMI
Power and Lighting Semiconductor

www.pnlsemi.com
+82-63-714-3737
smgoh@pnlsemi.com

Zener Diode List

Unidirectional Zener Diodes

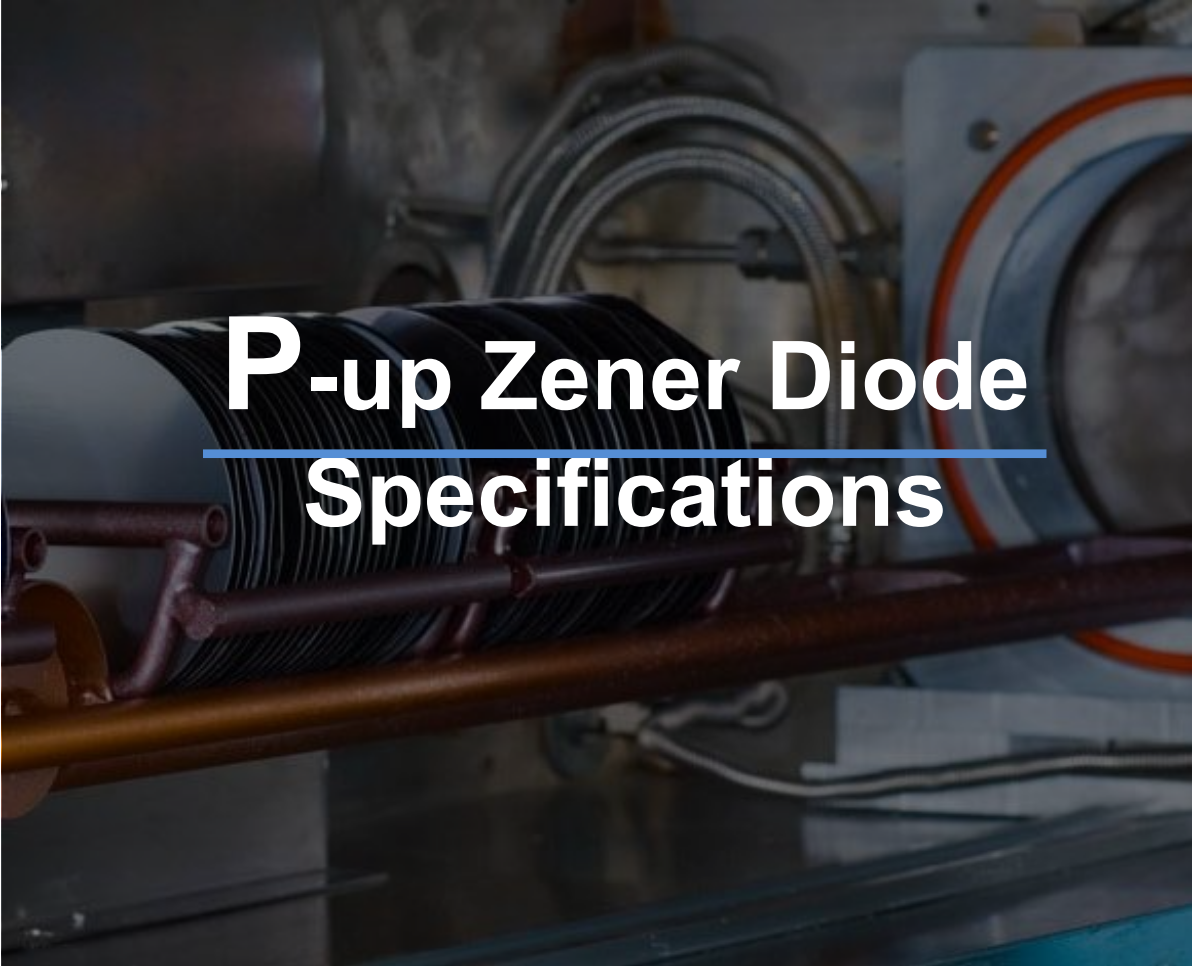
Product No.	Electrode	Die Size	Bonding PAD Size	Zener Voltage
	Common	[mm]	W x L [mm]	[V] (IR= 5mA)
PSZ-1017S	Cathode	0.150 x 0.150	0.120 x 0.120	7 / 8 / 12
PSZ-1017	Cathode	0.150 x 0.150	Ø 0.100	7 / 8 / 12
PSZ-1019	Cathode	0.170 x 0.170	Ø 0.090	6 / 7 / 12
PSZ-1021	Cathode	0.190 x 0.190	Ø 0.130	7 / 12 / 14
PSZ-1023	Cathode	0.210 x 0.210	Ø 0.150	7 / 8 / 12 / 30
PSZ-1026S	Cathode	0.240 x 0.240	0.180 x 0.180	7 / 12
PSZ-2017S	Anode	0.150 x 0.150	0.120 x 0.120	7 / 14
PSZ-2017	Anode	0.150 x 0.150	Ø 0.100	7 / 14
PSZ-2019	Anode	0.170 x 0.170	Ø 0.090	7 / 14
PSZ-2021	Anode	0.190 x 0.190	Ø 0.130	7 / 14
PSZ-2023	Anode	0.210 x 0.210	Ø 0.150	7 / 14
PSZ-2026S	Anode	0.240 x 0.240	0.180 x 0.180	7 / 14

Bidirectional Zener Diodes

Product No.	Electrode	Die Size	Bonding PAD Size	Zener Voltage
	Common	[mm]	W x L [mm]	[V] (IR= 5mA)
PSZ-1017B	N/P/N	0.150 x 0.150	0.120 x 0.120	7
PSZ-1021B	N/P/N	0.190 x 0.190	0.150 x 0.150	7
PSZ-1023B	N/P/N	0.210 x 0.210	0.160 x 0.160	7
PSZ-2021B	P/N/P	0.190 x 0.190	0.150 x 0.150	13
PSZ-1034D	P/N/P	0.320 x 0.320	0.116 x 0.265 (Dual Pad)	7
PSZ-2034D	N/P/N	0.320 x 0.320	0.116 x 0.265 (Dual Pad)	7

Flip Zener Diodes

Product No.	Electrode	Die Size	Bonding PAD Size	Zener Voltage
	Common	[mm]	W x L [mm]	[V] (IR= 5mA)
PSZ-1044023F	P/N/P	0.420 x 0.210	0.070 x 0.100 (Dual Pad)	8 / 20
PSZ-1049023F	P/N/P	0.470 x 0.210	0.100 x 0.110 (Dual Pad)	8 / 20
PSZ-1039039F	P/N/P	0.375 x 0.375	0.090 x 0.265 (Dual Pad)	8 / 20
PSZ-1056026F	P/N/P	0.540 x 0.240	0.200 x 0.200 (Dual Pad)	20

A photograph of industrial machinery, featuring a large, dark, cylindrical coil or spool of material, possibly a semiconductor wafer or a large capacitor, mounted on a metal frame. The background shows various mechanical components and pipes, suggesting a manufacturing or processing environment.

P-up Zener Diode Specifications

P&L SEMI
Power and Lighting Semiconductor

www.pnlsemi.com
+82-63-714-3737
smgoh@pnlsemi.com

Description

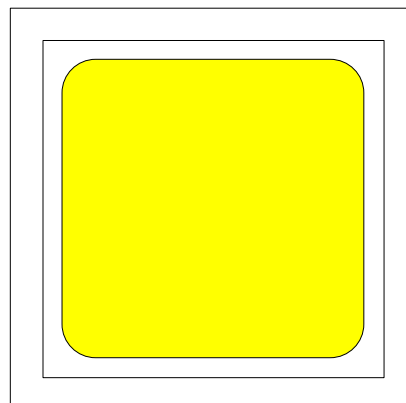
- PSZ-1017S-7V is silicon planar zener diode.
- Common cathode, anode is the bond pad on top.

Application

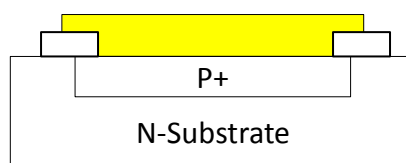
- ESD & Surge Protector for LEDs

Feature

- **Chip Size** : $150(\pm 20)\mu\text{m} \times 150(\pm 20)\mu\text{m}$
- **Chip Thickness** : $100\mu\text{m} \pm 15\mu\text{m}$
- **Structure** : Common Cathode
- **Metallization**
 - Top(Anode) : Au
 - Bottom(Cathode) : Au
- **Bonding Pad Size**
 - Top(Anode) : $\square 120\mu\text{m}$

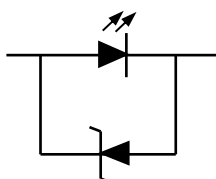


[Top View]



[Cross Section]

Schematic Diagram



Electrical and Optical Characteristics (Ta=25°C)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Forward Voltage	V_F	$I_F = 5\text{mA}$	0.7	0.9	1.2	V
Zener Voltage	V_Z	$I_Z = 5\text{mA}$	6	7	9	V
Reverse Current	I_R	$V_R = 4\text{V}$			0.1	μA

Absolute Maximum Rating (Ta=25°C)

Parameter	Symbol	Maximum Rating	Unit
Power dissipation	P_d	50	mW
Junction Temperature	T_j	150	°C

Description

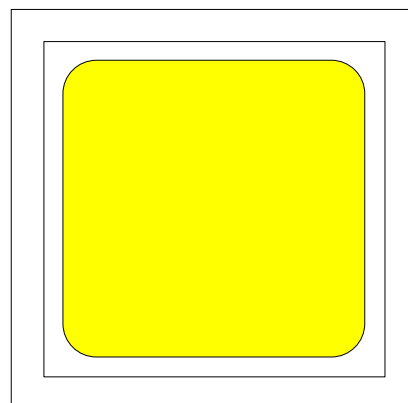
- PSZ-1017S-8V is silicon planar zener diode.
- Common cathode, anode is the bond pad on top.

Application

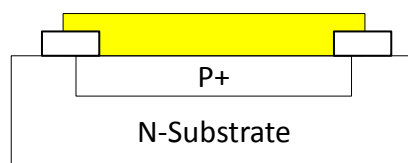
- ESD & Surge Protector for LEDs

Feature

- **Chip Size** : $150(\pm 20)\mu\text{m} \times 150(\pm 20)\mu\text{m}$
- **Chip Thickness** : $100\mu\text{m} \pm 15\mu\text{m}$
- **Structure** : Common Cathode
- **Metallization**
 - Top(Anode) : Au
 - Bottom(Cathode) : Au
- **Bonding Pad Size**
 - Top(Anode) : $\square 120\mu\text{m}$

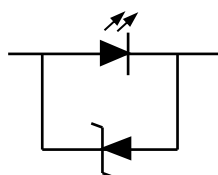


[Top View]



[Cross Section]

Schematic Diagram



Electrical and Optical Characteristics (Ta=25°C)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Forward Voltage	V_F	$I_F = 5\text{mA}$	0.7	0.9	1.2	V
Zener Voltage	V_Z	$I_Z = 5\text{mA}$	7	8	10	V
Reverse Current	I_R	$V_R = 4\text{V}$			0.1	μA

Absolute Maximum Rating (Ta=25°C)

Parameter	Symbol	Maximum Rating	Unit
Power dissipation	P_d	50	mW
Junction Temperature	T_j	150	°C

Description

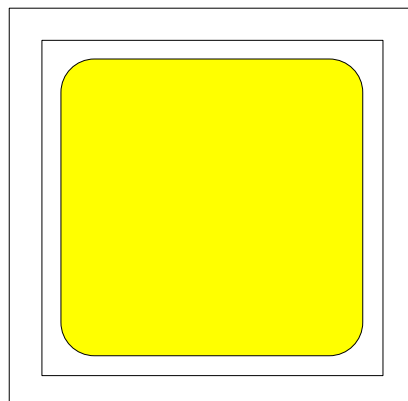
- PSZ-1017S-12V is silicon planar zener diode.
- Common cathode, anode is the bond pad on top.

Application

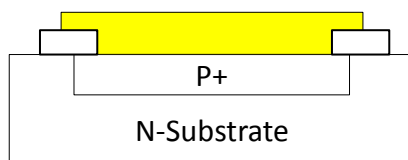
- ESD & Surge Protector for LEDs

Feature

- **Chip Size** : $150(\pm 20)\mu\text{m} \times 150(\pm 20)\mu\text{m}$
- **Chip Thickness** : $100\mu\text{m} \pm 15\mu\text{m}$
- **Structure** : Common Cathode
- **Metallization**
 - Top(Anode) : Au
 - Bottom(Cathode) : Au
- **Bonding Pad Size**
 - Top(Anode) : $\square 120\mu\text{m}$

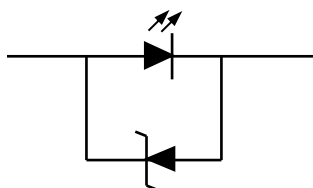


[Top View]



[Cross Section]

Schematic Diagram



Electrical and Optical Characteristics (Ta=25°C)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Forward Voltage	V_F	$I_F = 5\text{mA}$	0.7	0.9	1.2	V
Zener Voltage	V_Z	$I_Z = 5\text{mA}$	10	12	14	V
Reverse Current	I_R	$V_R = 4\text{V}$			0.1	μA

Absolute Maximum Rating (Ta=25°C)

Parameter	Symbol	Maximum Rating	Unit
Power dissipation	P_d	50	mW
Junction Temperature	T_j	150	°C

Description

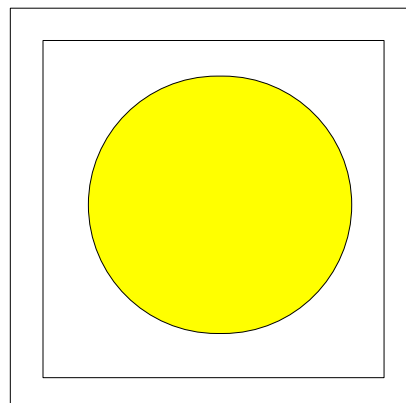
- PSZ-1017-7V is silicon planar zener diode.
- Common cathode, anode is the bond pad on top.

Application

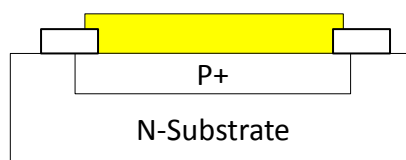
- ESD & Surge Protector for LEDs

Feature

- **Chip Size** : $150(\pm 20)\mu\text{m} \times 150(\pm 20)\mu\text{m}$
- **Chip Thickness** : $100\mu\text{m} \pm 15\mu\text{m}$
- **Structure** : Common Cathode
- **Metallization**
 - Top(Anode) : Au
 - Bottom(Cathode) : Au
- **Bonding Pad Size**
 - Top(Anode) : $\Phi 100\mu\text{m}$

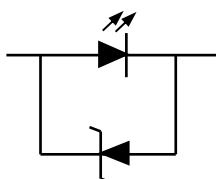


[Top View]



[Cross Section]

Schematic Diagram



Electrical and Optical Characteristics (Ta=25°C)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Forward Voltage	V_F	$I_F = 5\text{mA}$	0.7	0.9	1.2	V
Zener Voltage	V_Z	$I_Z = 5\text{mA}$	6	7	9	V
Reverse Current	I_R	$V_R = 4\text{V}$			0.1	μA

Absolute Maximum Rating (Ta=25°C)

Parameter	Symbol	Maximum Rating	Unit
Power dissipation	P_d	50	mW
Junction Temperature	T_j	150	°C

Description

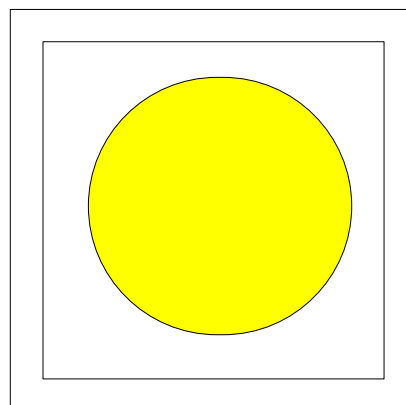
- PSZ-1017-8V is silicon planar zener diode.
- Common cathode, anode is the bond pad on top.

Application

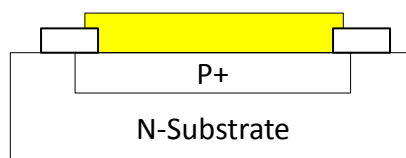
- ESD & Surge Protector for LEDs

Feature

- **Chip Size** : $150(\pm 20)\mu\text{m} \times 150(\pm 20)\mu\text{m}$
- **Chip Thickness** : $100\mu\text{m} \pm 15\mu\text{m}$
- **Structure** : Common Cathode
- **Metallization**
 - Top(Anode) : Au
 - Bottom(Cathode) : Au
- **Bonding Pad Size**
 - Top(Anode) : $\Phi 100\mu\text{m}$

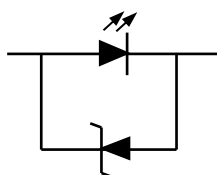


[Top View]



[Cross Section]

Schematic Diagram



Electrical and Optical Characteristics (Ta=25°C)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Forward Voltage	V_F	$I_F = 5\text{mA}$	0.7	0.9	1.2	V
Zener Voltage	V_Z	$I_Z = 5\text{mA}$	7	8	10	V
Reverse Current	I_R	$V_R = 4\text{V}$			0.1	μA

Absolute Maximum Rating (Ta=25°C)

Parameter	Symbol	Maximum Rating	Unit
Power dissipation	P_d	50	mW
Junction Temperature	T_j	150	°C

Description

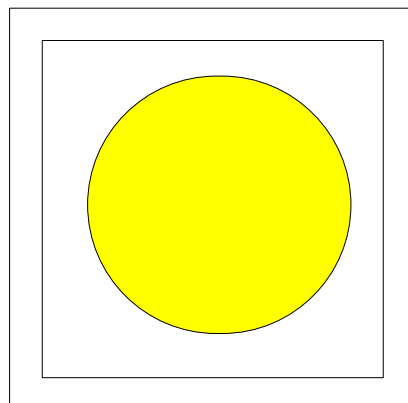
- PSZ-1017-12V is silicon planar zener diode.
- Common cathode, anode is the bond pad on top.

Application

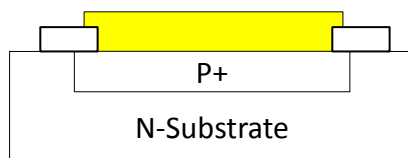
- ESD & Surge Protector for LEDs

Feature

- **Chip Size** : $150(\pm 20)\mu\text{m} \times 150(\pm 20)\mu\text{m}$
- **Chip Thickness** : $100\mu\text{m} \pm 15\mu\text{m}$
- **Structure** : Common Cathode
- **Metallization**
 - Top(Anode) : Au
 - Bottom(Cathode) : Au
- **Bonding Pad Size**
 - Top(Anode) : $\Phi 100\mu\text{m}$

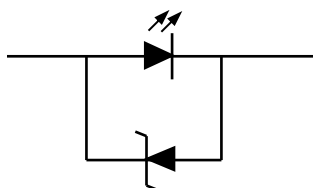


[Top View]



[Cross Section]

Schematic Diagram



Electrical and Optical Characteristics (Ta=25°C)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Forward Voltage	V_F	$I_F = 5\text{mA}$	0.7	0.9	1.2	V
Zener Voltage	V_Z	$I_Z = 5\text{mA}$	10	12	14	V
Reverse Current	I_R	$V_R = 8\text{V}$			0.1	μA

Absolute Maximum Rating (Ta=25°C)

Parameter	Symbol	Maximum Rating	Unit
Power dissipation	P_d	50	mW
Junction Temperature	T_j	150	°C

Description

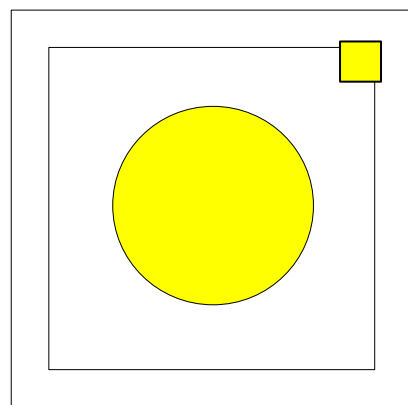
- PSZ-1019-6V is silicon planar zener diode.
- Common cathode, anode is the bond pad on top.

Application

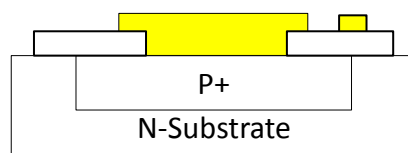
- ESD & Surge Protector for LEDs

Feature

- **Chip Size** : $170(\pm 20)\mu\text{m} \times 170(\pm 20)\mu\text{m}$
- **Chip Thickness** : $100\mu\text{m} \pm 15\mu\text{m}$
- **Structure** : Common Cathode
- **Metallization**
 - Top(Anode) : Au
 - Bottom(Cathode) : Au
- **Bonding Pad Size**
 - Top(Anode) : $\Phi 100\mu\text{m}$

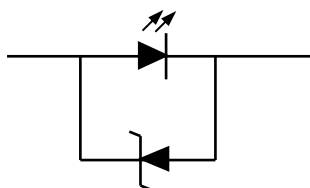


[Top View]



[Cross Section]

Schematic Diagram



Electrical and Optical Characteristics (Ta=25°C)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Forward Voltage	V_F	$I_F = 5\text{mA}$	0.7	0.9	1.2	V
Zener Voltage	V_Z	$I_Z = 5\text{mA}$	5.5	6.5	7.5	V
Reverse Current	I_R	$V_R = 3\text{V}$			0.1	μA

Absolute Maximum Rating (Ta=25°C)

Parameter	Symbol	Maximum Rating	Unit
Power dissipation	P_d	50	mW
Junction Temperature	T_j	150	°C

Description

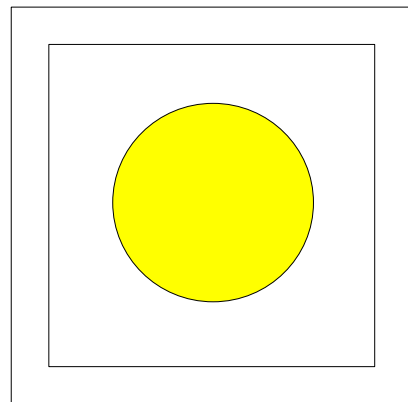
- PSZ-1019-7V is silicon planar zener diode.
- Common cathode, anode is the bond pad on top.

Application

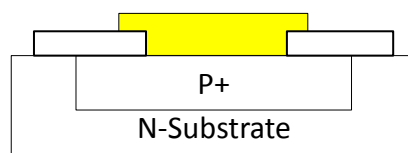
- ESD & Surge Protector for LEDs

Feature

- **Chip Size** : $170(\pm 20)\mu\text{m} \times 170(\pm 20)\mu\text{m}$
- **Chip Thickness** : $100\mu\text{m} \pm 15\mu\text{m}$
- **Structure** : Common Cathode
- **Metallization**
 - Top(Anode) : Au
 - Bottom(Cathode) : Au
- **Bonding Pad Size**
 - Top(Anode) : $\Phi 90\mu\text{m}$

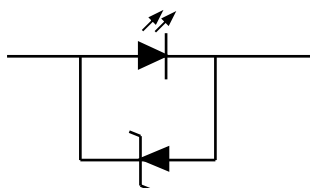


[Top View]



[Cross Section]

Schematic Diagram



Electrical and Optical Characteristics (Ta=25°C)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Forward Voltage	V_F	$I_F = 5\text{mA}$	0.7	0.9	1.2	V
Zener Voltage	V_Z	$I_Z = 5\text{mA}$	6	7	9	V
Reverse Current	I_R	$V_R = 4\text{V}$			0.1	μA

Absolute Maximum Rating (Ta=25°C)

Parameter	Symbol	Maximum Rating	Unit
Power dissipation	P_d	50	mW
Junction Temperature	T_j	150	°C

Description

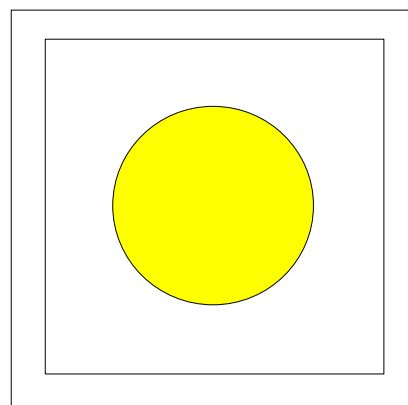
- PSZ-1019-12V is silicon planar zener diode.
- Common cathode, anode is the bond pad on top.

Application

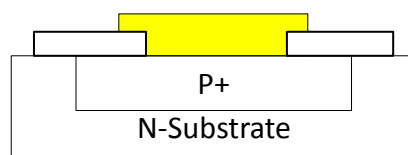
- ESD & Surge Protector for LEDs

Feature

- **Chip Size** : $170(\pm 20)\mu\text{m} \times 170(\pm 20)\mu\text{m}$
- **Chip Thickness** : $100\mu\text{m} \pm 15\mu\text{m}$
- **Structure** : Common Cathode
- **Metallization**
 - Top(Anode) : Au
 - Bottom(Cathode) : Au
- **Bonding Pad Size**
 - Top(Anode) : $\Phi 90\mu\text{m}$

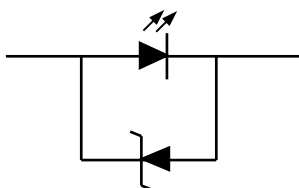


[Top View]



[Cross Section]

Schematic Diagram



Electrical and Optical Characteristics (Ta=25°C)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Forward Voltage	V_F	$I_F = 5\text{mA}$	0.7	0.9	1.2	V
Zener Voltage	V_Z	$I_Z = 5\text{mA}$	10	12	14	V
Reverse Current	I_R	$V_R = 4\text{V}$			0.1	μA

Absolute Maximum Rating (Ta=25°C)

Parameter	Symbol	Maximum Rating	Unit
Power dissipation	P_d	50	mW
Junction Temperature	T_j	150	°C

Description

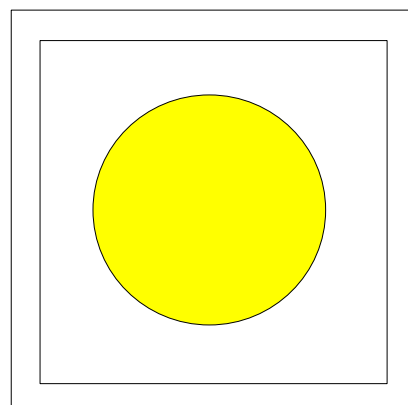
- PSZ-1021-7V is silicon planar zener diode.
- Common cathode, anode is the bond pad on top.

Application

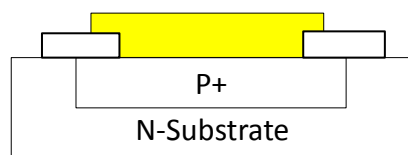
- ESD & Surge Protector for LEDs

Feature

- **Chip Size** : $190(\pm 20)\mu\text{m} \times 190(\pm 20)\mu\text{m}$
- **Chip Thickness** : $100\mu\text{m} \pm 15\mu\text{m}$
- **Structure** : Common Cathode
- **Metallization**
 - Top(Anode) : Au
 - Bottom(Cathode) : Au
- **Bonding Pad Size**
 - Top(Anode) : $\Phi 130\mu\text{m}$

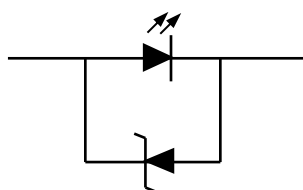


[Top View]



[Cross Section]

Schematic Diagram



Electrical and Optical Characteristics (Ta=25°C)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Forward Voltage	V_F	$I_F = 5\text{mA}$	0.7	0.9	1.2	V
Zener Voltage	V_Z	$I_Z = 5\text{mA}$	6	7	9	V
Reverse Current	I_R	$V_R = 4\text{V}$			0.1	μA

Absolute Maximum Rating (Ta=25°C)

Parameter	Symbol	Maximum Rating	Unit
Power dissipation	P_d	50	mW
Junction Temperature	T_j	150	°C

Description

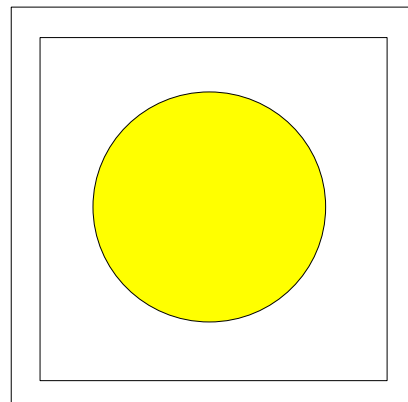
- PSZ-1021-12V is silicon planar zener diode.
- Common cathode, anode is the bond pad on top.

Application

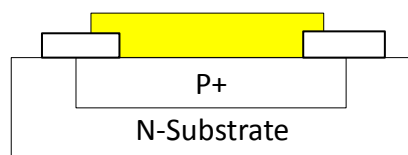
- ESD & Surge Protector for LEDs

Feature

- **Chip Size** : $190(\pm 20)\mu\text{m} \times 190(\pm 20)\mu\text{m}$
- **Chip Thickness** : $100\mu\text{m} \pm 15\mu\text{m}$
- **Structure** : Common Cathode
- **Metallization**
 - Top(Anode) : Au
 - Bottom(Cathode) : Au
- **Bonding Pad Size**
 - Top(Anode) : $\Phi 130\mu\text{m}$

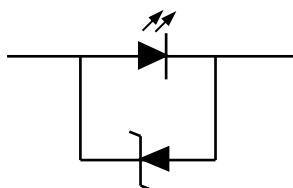


[Top View]



[Cross Section]

Schematic Diagram



Electrical and Optical Characteristics (Ta=25°C)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Forward Voltage	V_F	$I_F = 5\text{mA}$	0.7	0.9	1.2	V
Zener Voltage	V_Z	$I_Z = 5\text{mA}$	10	12	14	V
Reverse Current	I_R	$V_R = 8\text{V}$			0.1	μA

Absolute Maximum Rating (Ta=25°C)

Parameter	Symbol	Maximum Rating	Unit
Power dissipation	P_d	50	mW
Junction Temperature	T_j	150	°C

Description

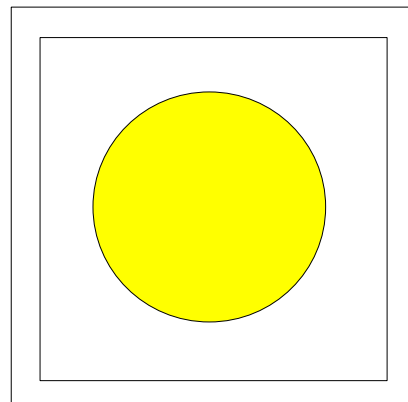
- PSZ-1021-14V is silicon planar zener diode.
- Common cathode, anode is the bond pad on top.

Application

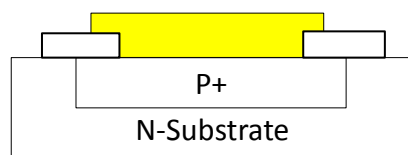
- ESD & Surge Protector for LEDs

Feature

- **Chip Size** : $190(\pm 20)\mu\text{m} \times 190(\pm 20)\mu\text{m}$
- **Chip Thickness** : $100\mu\text{m} \pm 15\mu\text{m}$
- **Structure** : Common Cathode
- **Metallization**
 - Top(Anode) : Au
 - Bottom(Cathode) : Au
- **Bonding Pad Size**
 - Top(Anode) : $\Phi 130\mu\text{m}$

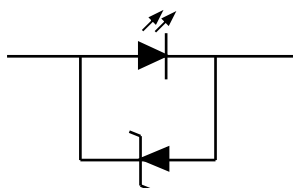


[Top View]



[Cross Section]

Schematic Diagram



Electrical and Optical Characteristics (Ta=25°C)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Forward Voltage	V_F	$I_F = 5\text{mA}$	0.7	0.9	1.2	V
Zener Voltage	V_Z	$I_Z = 5\text{mA}$	12	14	16	V
Reverse Current	I_R	$V_R = 8\text{V}$			0.1	μA

Absolute Maximum Rating (Ta=25°C)

Parameter	Symbol	Maximum Rating	Unit
Power dissipation	P_d	50	mW
Junction Temperature	T_j	150	°C

Description

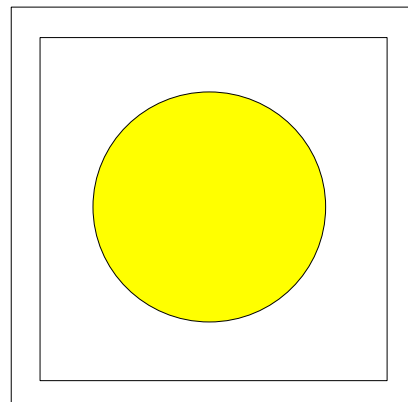
- PSZ-1023-7V is silicon planar zener diode.
- Common cathode, anode is the bond pad on top.

Application

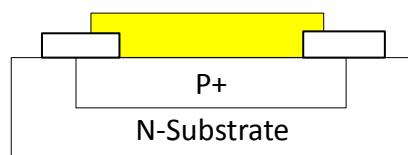
- ESD & Surge Protector for LEDs

Feature

- **Chip Size** : $210(\pm 20)\mu\text{m} \times 210(\pm 20)\mu\text{m}$
- **Chip Thickness** : $100\mu\text{m} \pm 15\mu\text{m}$
- **Structure** : Common Cathode
- **Metallization**
 - Top(Anode) : Au
 - Bottom(Cathode) : Au
- **Bonding Pad Size**
 - Top(Anode) : $\Phi 150\mu\text{m}$

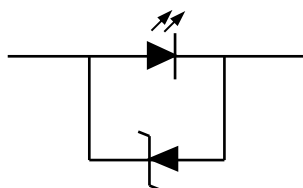


[Top View]



[Cross Section]

Schematic Diagram



Electrical and Optical Characteristics (Ta=25°C)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Forward Voltage	V_F	$I_F = 5\text{mA}$	0.7	0.9	1.2	V
Zener Voltage	V_Z	$I_Z = 5\text{mA}$	6	7	9	V
Reverse Current	I_R	$V_R = 4\text{V}$			0.1	μA

Absolute Maximum Rating (Ta=25°C)

Parameter	Symbol	Maximum Rating	Unit
Power dissipation	P_d	100	mW
Junction Temperature	T_j	150	°C

Description

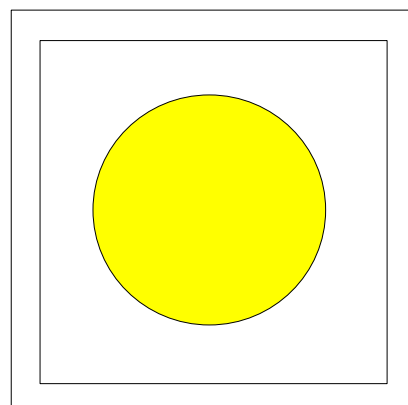
- PSZ-1023-8V is silicon planar zener diode.
- Common cathode, anode is the bond pad on top.

Application

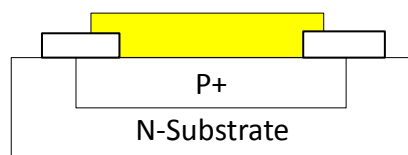
- ESD & Surge Protector for LEDs

Feature

- **Chip Size** : $210(\pm 20)\mu\text{m} \times 210(\pm 20)\mu\text{m}$
- **Chip Thickness** : $100\mu\text{m} \pm 15\mu\text{m}$
- **Structure** : Common Cathode
- **Metallization**
 - Top(Anode) : Au
 - Bottom(Cathode) : Au
- **Bonding Pad Size**
 - Top(Anode) : $\Phi 150\mu\text{m}$

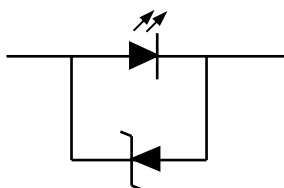


[Top View]



[Cross Section]

Schematic Diagram



Electrical and Optical Characteristics (Ta=25°C)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Forward Voltage	V_F	$I_F = 5\text{mA}$	0.7	0.9	1.2	V
Zener Voltage	V_Z	$I_Z = 5\text{mA}$	7	8	10	V
Reverse Current	I_R	$V_R = 4\text{V}$			0.1	μA

Absolute Maximum Rating (Ta=25°C)

Parameter	Symbol	Maximum Rating	Unit
Power dissipation	P_d	100	mW
Junction Temperature	T_j	150	°C

Description

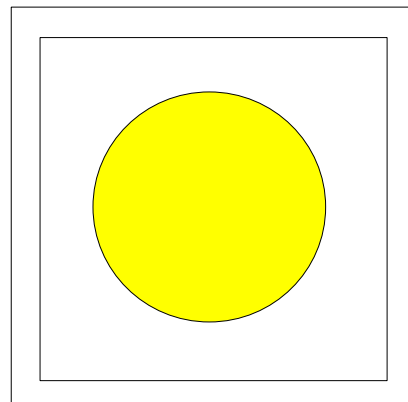
- PSZ-1023-12V is silicon planar zener diode.
- Common cathode, anode is the bond pad on top.

Application

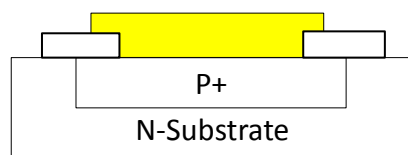
- ESD & Surge Protector for LEDs

Feature

- **Chip Size** : $210(\pm 20)\mu\text{m} \times 210(\pm 20)\mu\text{m}$
- **Chip Thickness** : $100\mu\text{m} \pm 15\mu\text{m}$
- **Structure** : Common Cathode
- **Metallization**
 - Top(Anode) : Au
 - Bottom(Cathode) : Au
- **Bonding Pad Size**
 - Top(Anode) : $\Phi 150\mu\text{m}$

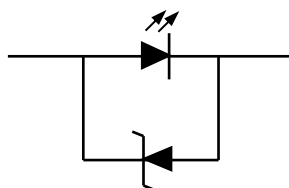


[Top View]



[Cross Section]

Schematic Diagram



Electrical and Optical Characteristics (Ta=25°C)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Forward Voltage	V_F	$I_F = 5\text{mA}$	0.7	0.9	1.2	V
Zener Voltage	V_Z	$I_Z = 5\text{mA}$	10	12	14	V
Reverse Current	I_R	$V_R = 8\text{V}$			0.1	μA

Absolute Maximum Rating (Ta=25°C)

Parameter	Symbol	Maximum Rating	Unit
Power dissipation	P_d	100	mW
Junction Temperature	T_j	150	°C

Description

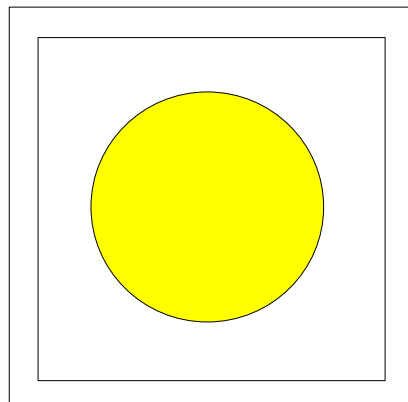
- PSZ-1023-30V is silicon planar zener diode.
- Common cathode, anode is the bond pad on top.

Application

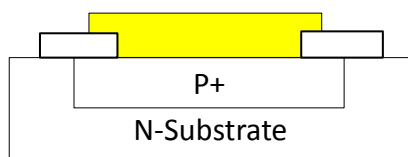
- ESD & Surge Protector for LEDs

Feature

- **Chip Size** : $210(\pm 20)\mu\text{m} \times 210(\pm 20)\mu\text{m}$
- **Chip Thickness** : $100\mu\text{m} \pm 15\mu\text{m}$
- **Structure** : Common Cathode
- **Metallization**
 - Top(Anode) : Au
 - Bottom(Cathode) : Au
- **Bonding Pad Size**
 - Top(Anode) : $\Phi 150\mu\text{m}$

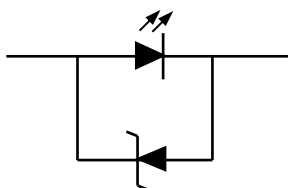


[Top View]



[Cross Section]

Schematic Diagram



Electrical and Optical Characteristics (Ta=25°C)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Forward Voltage	V_F	$I_F = 5\text{mA}$	0.7	0.9	1.2	V
Zener Voltage	V_Z	$I_Z = 5\text{mA}$	25	30	35	V
Reverse Current	I_R	$V_R = 20\text{V}$			0.1	μA

Absolute Maximum Rating (Ta=25°C)

Parameter	Symbol	Maximum Rating	Unit
Power dissipation	P_d	100	mW
Junction Temperature	T_j	150	°C

Description

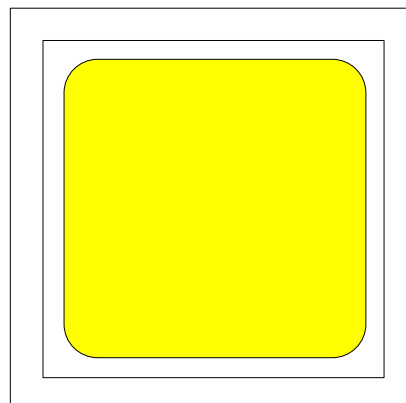
- PSZ-1026S-7V is silicon planar zener diode.
- Common cathode, anode is the bond pad on top.

Application

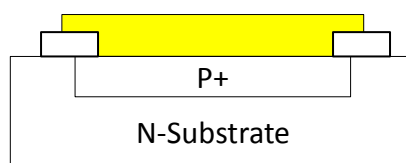
- ESD & Surge Protector for LEDs

Feature

- **Chip Size** : $240(\pm 20)\mu\text{m} \times 240(\pm 20)\mu\text{m}$
- **Chip Thickness** : $100\mu\text{m} \pm 15\mu\text{m}$
- **Structure** : Common Cathode
- **Metallization**
 - Top(Anode) : Au
 - Bottom(Cathode) : Au
- **Bonding Pad Size**
 - Top(Anode) : $\square 180\mu\text{m}$

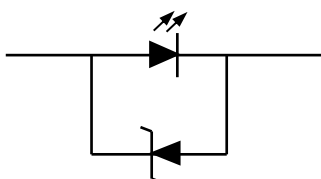


[Top View]



[Cross Section]

Schematic Diagram



Electrical and Optical Characteristics (Ta=25°C)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Forward Voltage	V_F	$I_F = 5\text{mA}$	0.7	0.9	1.2	V
Zener Voltage	V_Z	$I_Z = 5\text{mA}$	6	7	9	V
Reverse Current	I_R	$V_R = 4\text{V}$			0.1	μA

Absolute Maximum Rating (Ta=25°C)

Parameter	Symbol	Maximum Rating	Unit
Power dissipation	P_d	100	mW
Junction Temperature	T_j	150	°C

Description

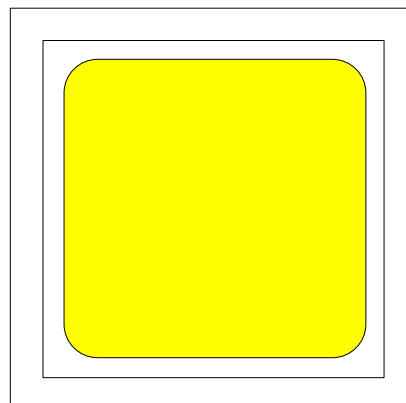
- PSZ-1026S-12V is silicon planar zener diode.
- Common cathode, anode is the bond pad on top.

Application

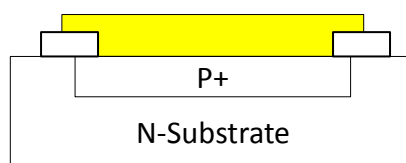
- ESD & Surge Protector for LEDs

Feature

- **Chip Size** : $240(\pm 20)\mu\text{m} \times 240(\pm 20)\mu\text{m}$
- **Chip Thickness** : $100\mu\text{m} \pm 15\mu\text{m}$
- **Structure** : Common Cathode
- **Metallization**
 - Top(Anode) : Au
 - Bottom(Cathode) : Au
- **Bonding Pad Size**
 - Top(Anode) : $\square 180\mu\text{m}$

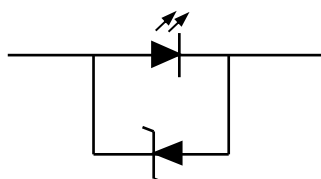


[Top View]



[Cross Section]

Schematic Diagram

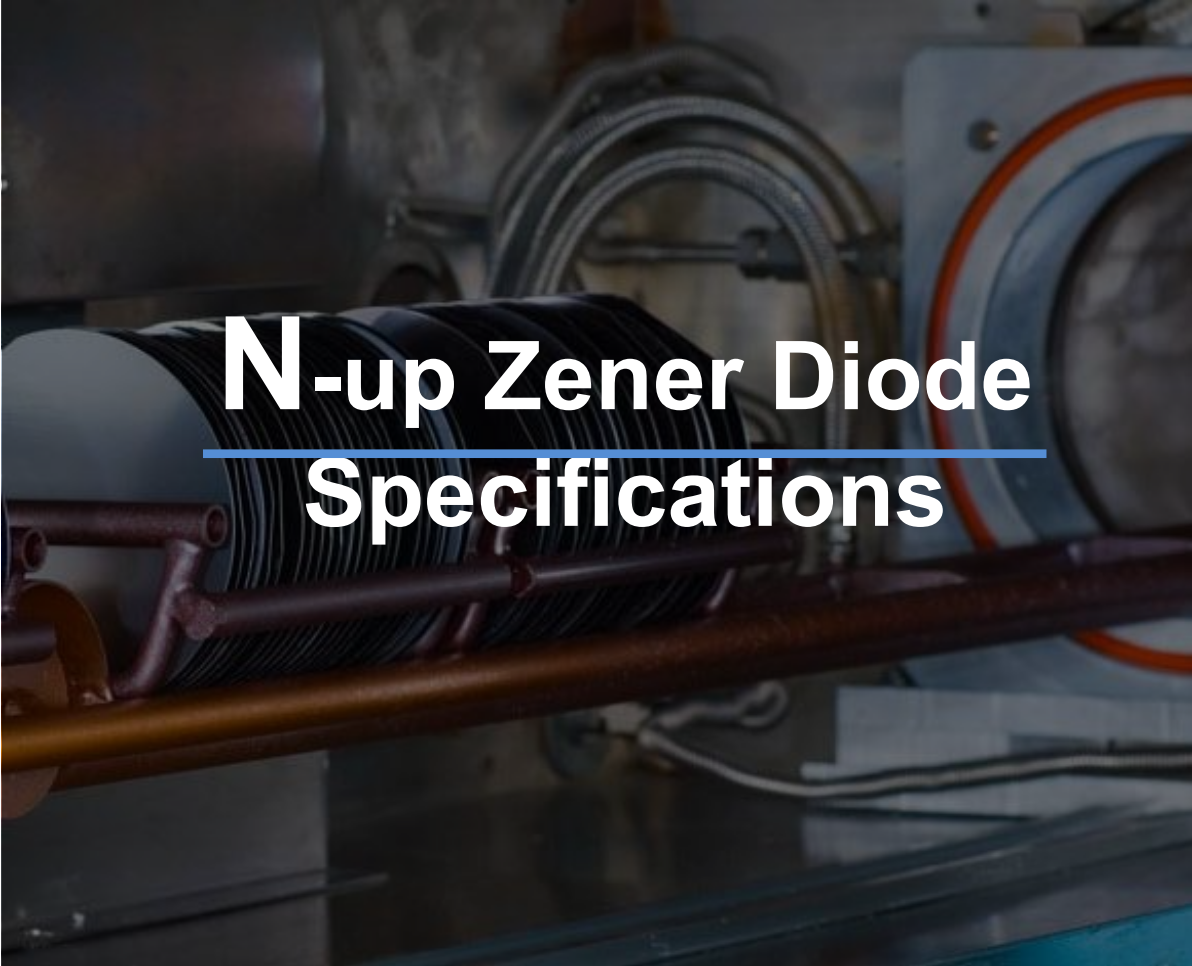


Electrical and Optical Characteristics (Ta=25°C)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Forward Voltage	V_F	$I_F = 5\text{mA}$	0.7	0.9	1.2	V
Zener Voltage	V_Z	$I_Z = 5\text{mA}$	10	12	14	V
Reverse Current	I_R	$V_R = 8\text{V}$			0.1	μA

Absolute Maximum Rating (Ta=25°C)

Parameter	Symbol	Maximum Rating	Unit
Power dissipation	P_d	100	mW
Junction Temperature	T_j	150	°C



N-up Zener Diode Specifications

P&L SEMI
Power and Lighting Semiconductor

www.pnlsemi.com
+82-63-714-3737
smgoh@pnlsemi.com

Description

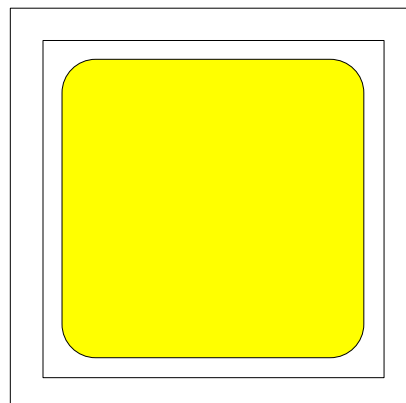
- PSZ-2017S-7V is silicon planar zener diode.
- Common anode, cathode is the bond pad on top.

Application

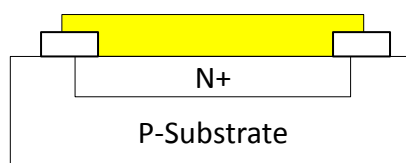
- ESD & Surge Protector for LEDs

Feature

- **Chip Size** : $150(\pm 20)\mu\text{m} \times 150(\pm 20)\mu\text{m}$
- **Chip Thickness** : $100\mu\text{m} \pm 15\mu\text{m}$
- **Structure** : Common Anode
- **Metallization**
 - Top(Cathode) : Au
 - Bottom(Anode) : Au
- **Bonding Pad Size**
 - Top(Cathode) : $\square 120\mu\text{m}$

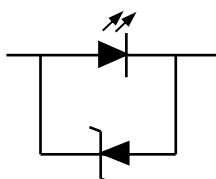


[Top View]



[Cross Section]

Schematic Diagram



Electrical and Optical Characteristics (Ta=25°C)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Forward Voltage	V_F	$I_F = 5\text{mA}$	0.7	0.9	1.2	V
Zener Voltage	V_Z	$I_Z = 5\text{mA}$	6	7	9	V
Reverse Current	I_R	$V_R = 4\text{V}$			0.1	μA

Absolute Maximum Rating (Ta=25°C)

Parameter	Symbol	Maximum Rating	Unit
Power dissipation	P_d	50	mW
Junction Temperature	T_j	150	°C

Description

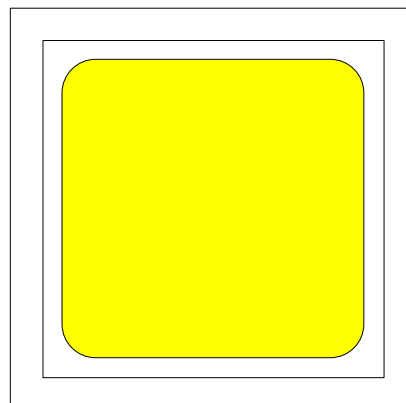
- PSZ-2017S-14V is silicon planar zener diode.
- Common anode, cathode is the bond pad on top.

Application

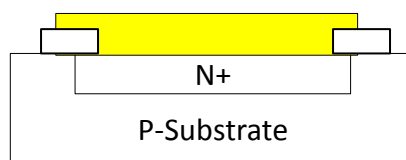
- ESD & Surge Protector for LEDs

Feature

- **Chip Size** : $150(\pm 20)\mu\text{m} \times 150(\pm 20)\mu\text{m}$
- **Chip Thickness** : $100\mu\text{m} \pm 15\mu\text{m}$
- **Structure** : Common Anode
- **Metallization**
 - Top(Cathode) : Au
 - Bottom(Anode) : Au
- **Bonding Pad Size**
 - Top(Cathode) : $\square 120\mu\text{m}$

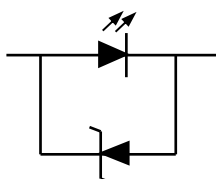


[Top View]



[Cross Section]

Schematic Diagram



Electrical and Optical Characteristics (Ta=25°C)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Forward Voltage	V_F	$I_F = 5\text{mA}$	0.7	0.9	1.2	V
Zener Voltage	V_Z	$I_Z = 5\text{mA}$	12	14	16	V
Reverse Current	I_R	$V_R = 8\text{V}$			0.1	μA

Absolute Maximum Rating (Ta=25°C)

Parameter	Symbol	Maximum Rating	Unit
Power dissipation	P_d	50	mW
Junction Temperature	T_j	150	°C

Description

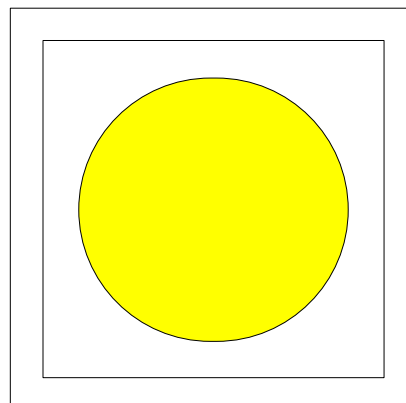
- PSZ-2017-7V is silicon planar zener diode.
- Common anode, cathode is the bond pad on top.

Application

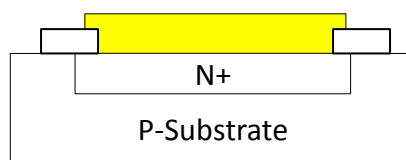
- ESD & Surge Protector for LEDs

Feature

- **Chip Size** : $150(\pm 20)\mu\text{m} \times 150(\pm 20)\mu\text{m}$
- **Chip Thickness** : $100\mu\text{m} \pm 15\mu\text{m}$
- **Structure** : Common Anode
- **Metallization**
 - Top(Cathode) : Au
 - Bottom(Anode) : Au
- **Bonding Pad Size**
 - Top(Cathode) : $\Phi 100\mu\text{m}$

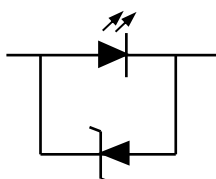


[Top View]



[Cross Section]

Schematic Diagram



Electrical and Optical Characteristics (Ta=25°C)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Forward Voltage	V_F	$I_F = 5\text{mA}$	0.7	0.9	1.2	V
Zener Voltage	V_Z	$I_Z = 5\text{mA}$	6	7	9	V
Reverse Current	I_R	$V_R = 4\text{V}$			0.1	μA

Absolute Maximum Rating (Ta=25°C)

Parameter	Symbol	Maximum Rating	Unit
Power dissipation	P_d	50	mW
Junction Temperature	T_j	150	°C

Description

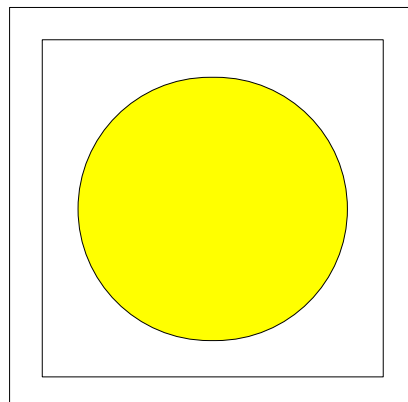
- PSZ-2017-14V is silicon planar zener diode.
- Common anode, cathode is the bond pad on top.

Application

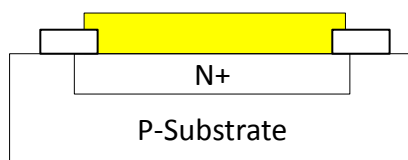
- ESD & Surge Protector for LEDs

Feature

- **Chip Size** : $150(\pm 20)\mu\text{m} \times 150(\pm 20)\mu\text{m}$
- **Chip Thickness** : $100\mu\text{m} \pm 15\mu\text{m}$
- **Structure** : Common Anode
- **Metallization**
 - Top(Cathode) : Au
 - Bottom(Anode) : Au
- **Bonding Pad Size**
 - Top(Cathode) : $\Phi 100\mu\text{m}$

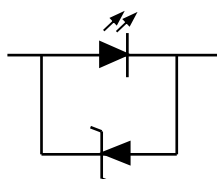


[Top View]



[Cross Section]

Schematic Diagram



Electrical and Optical Characteristics (Ta=25°C)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Forward Voltage	V_F	$I_F = 5\text{mA}$	0.7	0.9	1.2	V
Zener Voltage	V_Z	$I_Z = 5\text{mA}$	12	14	16	V
Reverse Current	I_R	$V_R = 8\text{V}$			0.1	μA

Absolute Maximum Rating (Ta=25°C)

Parameter	Symbol	Maximum Rating	Unit
Power dissipation	P_d	50	mW
Junction Temperature	T_j	150	°C

Description

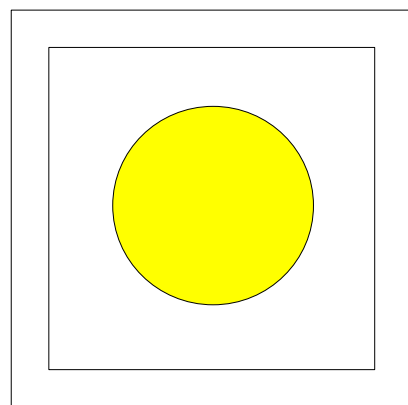
- PSZ-2019-7V is silicon planar zener diode.
- Common anode, cathode is the bond pad on top.

Application

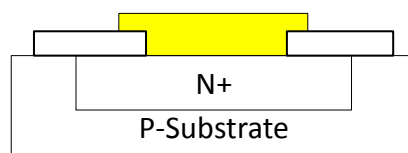
- ESD & Surge Protector for LEDs

Feature

- **Chip Size** : $170(\pm 20)\mu\text{m} \times 170(\pm 20)\mu\text{m}$
- **Chip Thickness** : $100\mu\text{m} \pm 15\mu\text{m}$
- **Structure** : Common Anode
- **Metallization**
 - Top(Cathode) : Au
 - Bottom(Anode) : Au
- **Bonding Pad Size**
 - Top(Cathode) : $\Phi 90\mu\text{m}$

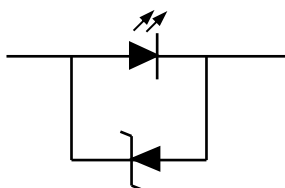


[Top View]



[Cross Section]

Schematic Diagram



Electrical and Optical Characteristics (Ta=25°C)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Forward Voltage	V_F	$I_F = 5\text{mA}$	0.7	0.9	1.2	V
Zener Voltage	V_Z	$I_Z = 5\text{mA}$	6	7	9	V
Reverse Current	I_R	$V_R = 4\text{V}$			0.1	μA

Absolute Maximum Rating (Ta=25°C)

Parameter	Symbol	Maximum Rating	Unit
Power dissipation	P_d	50	mW
Junction Temperature	T_j	150	°C

Description

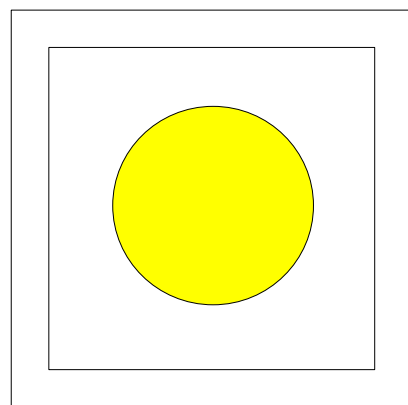
- PSZ-2019-14V is silicon planar zener diode.
- Common anode, cathode is the bond pad on top.

Application

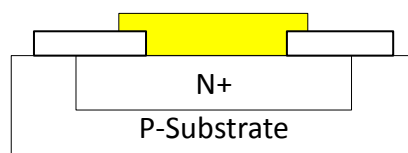
- ESD & Surge Protector for LEDs

Feature

- **Chip Size** : $170(\pm 20)\mu\text{m} \times 170(\pm 20)\mu\text{m}$
- **Chip Thickness** : $100\mu\text{m} \pm 15\mu\text{m}$
- **Structure** : Common Anode
- **Metallization**
 - Top(Cathode) : Au
 - Bottom(Anode) : Au
- **Bonding Pad Size**
 - Top(Cathode) : $\Phi 90\mu\text{m}$

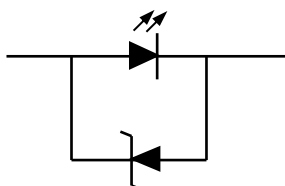


[Top View]



[Cross Section]

Schematic Diagram



Electrical and Optical Characteristics (Ta=25°C)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Forward Voltage	V_F	$I_F = 5\text{mA}$	0.7	0.9	1.2	V
Zener Voltage	V_Z	$I_Z = 5\text{mA}$	12	14	16	V
Reverse Current	I_R	$V_R = 8\text{V}$			0.1	μA

Absolute Maximum Rating (Ta=25°C)

Parameter	Symbol	Maximum Rating	Unit
Power dissipation	P_d	50	mW
Junction Temperature	T_j	150	°C

Description

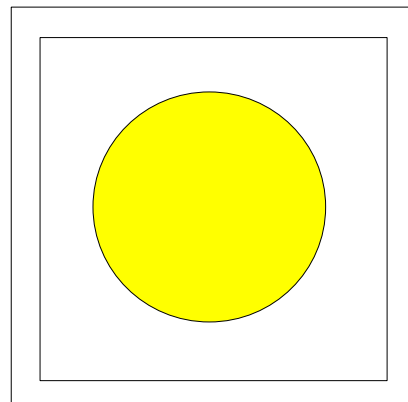
- PSZ-2021-7V is silicon planar zener diode.
- Common anode, cathode is the bond pad on top.

Application

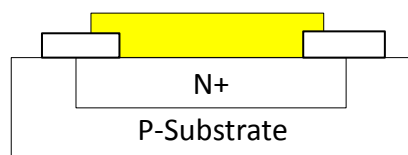
- ESD & Surge Protector for LEDs

Feature

- **Chip Size** : $190(\pm 20)\mu\text{m} \times 190(\pm 20)\mu\text{m}$
- **Chip Thickness** : $100\mu\text{m} \pm 15\mu\text{m}$
- **Structure** : Common Anode
- **Metallization**
 - Top(Cathode) : Au
 - Bottom(Anode) : Au
- **Bonding Pad Size**
 - Top(Cathode) : $\Phi 130\mu\text{m}$

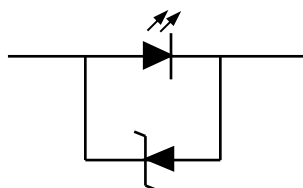


[Top View]



[Cross Section]

Schematic Diagram



Electrical and Optical Characteristics (Ta=25°C)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Forward Voltage	V_F	$I_F = 5\text{mA}$	0.7	0.9	1.2	V
Zener Voltage	V_Z	$I_Z = 5\text{mA}$	6	7	9	V
Reverse Current	I_R	$V_R = 4\text{V}$			0.1	μA

Absolute Maximum Rating (Ta=25°C)

Parameter	Symbol	Maximum Rating	Unit
Power dissipation	P_d	50	mW
Junction Temperature	T_j	150	°C

Description

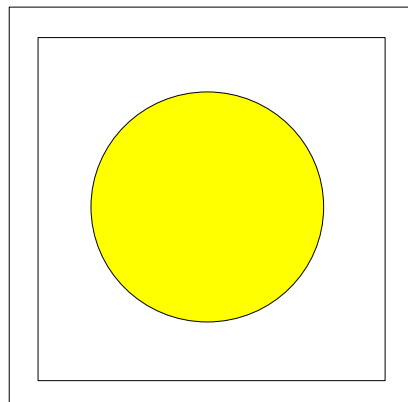
- PSZ-2021-14V is silicon planar zener diode.
- Common anode, cathode is the bond pad on top.

Application

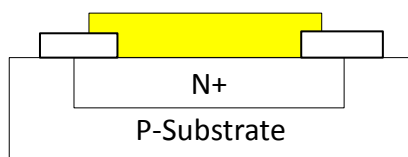
- ESD & Surge Protector for LEDs

Feature

- **Chip Size** : $190(\pm 20)\mu\text{m} \times 190(\pm 20)\mu\text{m}$
- **Chip Thickness** : $100\mu\text{m} \pm 15\mu\text{m}$
- **Structure** : Common Anode
- **Metallization**
 - Top(Cathode) : Au
 - Bottom(Anode) : Au
- **Bonding Pad Size**
 - Top(Cathode) : $\Phi 130\mu\text{m}$

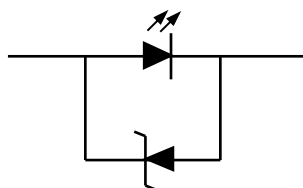


[Top View]



[Cross Section]

Schematic Diagram



Electrical and Optical Characteristics (Ta=25°C)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Forward Voltage	V_F	$I_F = 5\text{mA}$	0.7	0.9	1.2	V
Zener Voltage	V_Z	$I_Z = 5\text{mA}$	12	14	16	V
Reverse Current	I_R	$V_R = 8\text{V}$			0.1	μA

Absolute Maximum Rating (Ta=25°C)

Parameter	Symbol	Maximum Rating	Unit
Power dissipation	P_d	50	mW
Junction Temperature	T_j	150	°C

Description

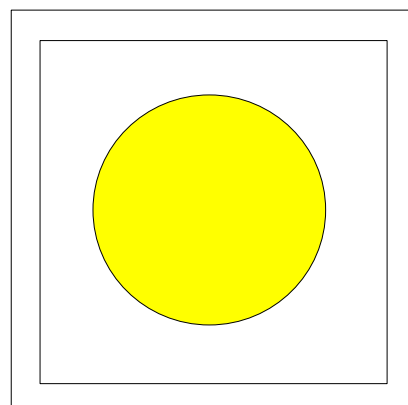
- PSZ-2023-7V is silicon planar zener diode.
- Common anode, cathode is the bond pad on top.

Application

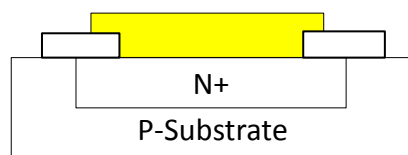
- ESD & Surge Protector for LEDs

Feature

- **Chip Size** : $210(\pm 20)\mu\text{m} \times 210(\pm 20)\mu\text{m}$
- **Chip Thickness** : $100\mu\text{m} \pm 15\mu\text{m}$
- **Structure** : Common Anode
- **Metallization**
 - Top(Cathode) : Au
 - Bottom(Anode) : Au
- **Bonding Pad Size**
 - Top(Cathode) : $\Phi 150\mu\text{m}$

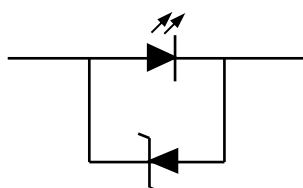


[Top View]



[Cross Section]

Schematic Diagram



Electrical and Optical Characteristics (Ta=25°C)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Forward Voltage	V_F	$I_F = 5\text{mA}$	0.7	0.9	1.2	V
Zener Voltage	V_Z	$I_Z = 5\text{mA}$	6	7	9	V
Reverse Current	I_R	$V_R = 4\text{V}$			0.1	μA

Absolute Maximum Rating (Ta=25°C)

Parameter	Symbol	Maximum Rating	Unit
Power dissipation	P_d	100	mW
Junction Temperature	T_j	150	°C

Description

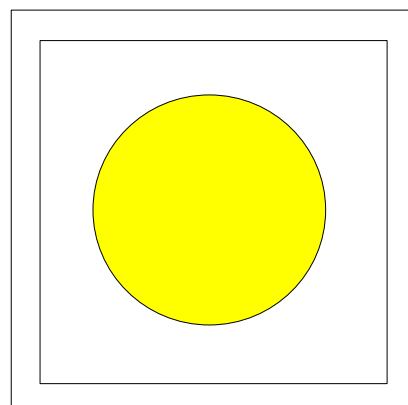
- PSZ-2023-14V is silicon planar zener diode.
- Common anode, cathode is the bond pad on top.

Application

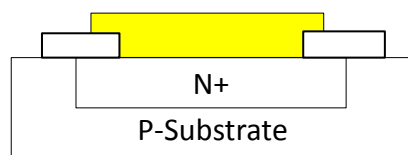
- ESD & Surge Protector for LEDs

Feature

- **Chip Size** : $210(\pm 20)\mu\text{m} \times 210(\pm 20)\mu\text{m}$
- **Chip Thickness** : $100\mu\text{m} \pm 15\mu\text{m}$
- **Structure** : Common Anode
- **Metallization**
 - Top(Cathode) : Au
 - Bottom(Anode) : Au
- **Bonding Pad Size**
 - Top(Cathode) : $\Phi 150\mu\text{m}$

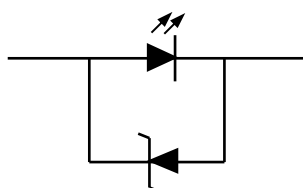


[Top View]



[Cross Section]

Schematic Diagram



Electrical and Optical Characteristics (Ta=25°C)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Forward Voltage	V_F	$I_F = 5\text{mA}$	0.7	0.9	1.2	V
Zener Voltage	V_Z	$I_Z = 5\text{mA}$	12	14	16	V
Reverse Current	I_R	$V_R = 8\text{V}$			0.1	μA

Absolute Maximum Rating (Ta=25°C)

Parameter	Symbol	Maximum Rating	Unit
Power dissipation	P_d	100	mW
Junction Temperature	T_j	150	°C

Description

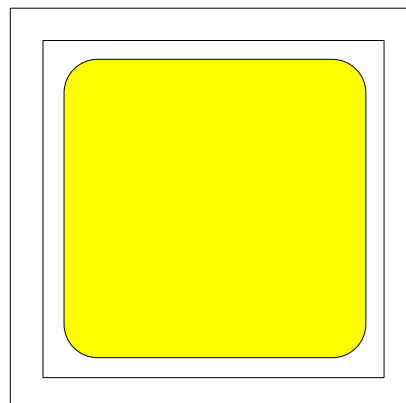
- PSZ-2026S-7V is silicon planar zener diode.
- Common anode, cathode is the bond pad on top.

Application

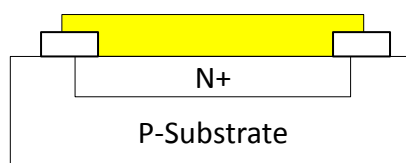
- ESD & Surge Protector for LEDs

Feature

- **Chip Size** : $240(\pm 20)\mu\text{m} \times 240(\pm 20)\mu\text{m}$
- **Chip Thickness** : $100\mu\text{m} \pm 15\mu\text{m}$
- **Structure** : Common Anode
- **Metallization**
 - Top(Cathode) : Au
 - Bottom(Anode) : Au
- **Bonding Pad Size**
 - Top(Cathode) : $\square 180\mu\text{m}$

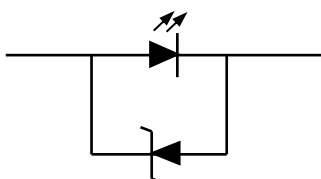


[Top View]



[Cross Section]

Schematic Diagram



Electrical and Optical Characteristics (Ta=25°C)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Forward Voltage	V_F	$I_F = 5\text{mA}$	0.7	0.9	1.2	V
Zener Voltage	V_Z	$I_Z = 5\text{mA}$	6	7	9	V
Reverse Current	I_R	$V_R = 4\text{V}$			0.1	μA

Absolute Maximum Rating (Ta=25°C)

Parameter	Symbol	Maximum Rating	Unit
Power dissipation	P_d	100	mW
Junction Temperature	T_j	150	°C

Description

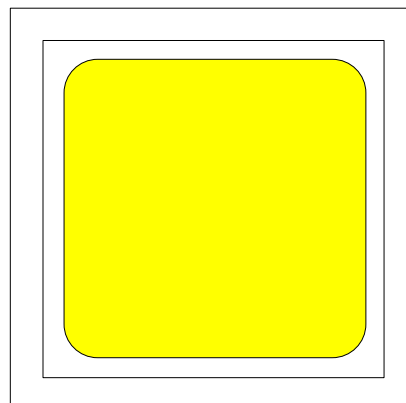
- PSZ-2026S-14V is silicon planar zener diode.
- Common anode, cathode is the bond pad on top.

Application

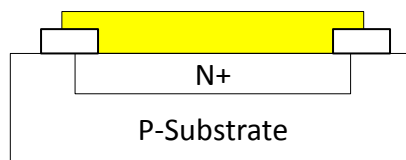
- ESD & Surge Protector for LEDs

Feature

- **Chip Size** : $240(\pm 20)\mu\text{m} \times 240(\pm 20)\mu\text{m}$
- **Chip Thickness** : $100\mu\text{m} \pm 15\mu\text{m}$
- **Structure** : Common Anode
- **Metallization**
 - Top(Cathode) : Au
 - Bottom(Anode) : Au
- **Bonding Pad Size**
 - Top(Cathode) : $\square 180\mu\text{m}$

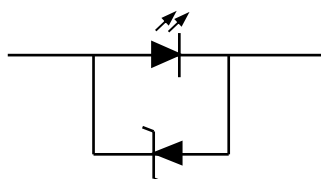


[Top View]



[Cross Section]

Schematic Diagram



Electrical and Optical Characteristics (Ta=25°C)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Forward Voltage	V_F	$I_F = 5\text{mA}$	0.7	0.9	1.2	V
Zener Voltage	V_Z	$I_Z = 5\text{mA}$	12	14	16	V
Reverse Current	I_R	$V_R = 8\text{V}$			0.1	μA

Absolute Maximum Rating (Ta=25°C)

Parameter	Symbol	Maximum Rating	Unit
Power dissipation	P_d	100	mW
Junction Temperature	T_j	150	°C

A background image showing industrial machinery, possibly a manufacturing process for semiconductor components, with a focus on a large, dark, cylindrical object.

Bidirection Zener Diode Specifications

P&L SEMI
Power and Lighting Semiconductor

www.pnlsemi.com
+82-63-714-3737
smgoh@pnlsemi.com

Description

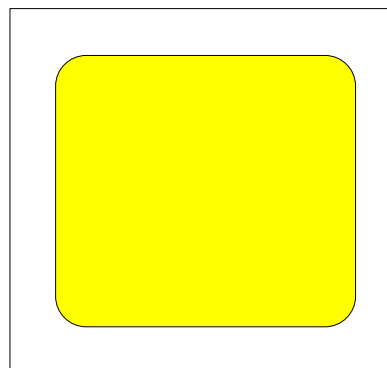
- PSZ-1017B-7V is silicon planar zener diode.
- $V_{Z(F)}$ means Zener voltage on forward bias.

Application

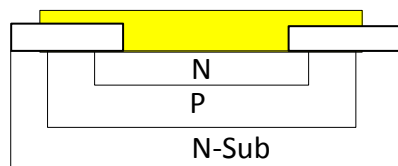
- ESD & Surge Protector for LEDs

Feature

- **Chip Size** : $150(\pm 20)\mu\text{m} \times 150(\pm 20)\mu\text{m}$
- **Chip Thickness** : $100\mu\text{m} \pm 15\mu\text{m}$
- **Structure** : Vertical N/P/N
- **Metallization**
 - Top(Anode) : Au
 - Bottom(Cathode) : Au
- **Bonding Pad Size**
 - Top(Anode) : $\square 115\mu\text{m}$

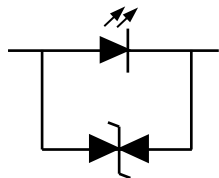


[Top View]



[Cross Section]

Schematic Diagram



Electrical and Optical Characteristics (Ta=25°C)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Forward Zener Voltage	$V_{Z(F)}$	$I_F = 5\text{mA}$	4.5	5.5	7	V
Reverse Zener Voltage	$V_{Z(R)}$	$I_Z = 5\text{mA}$	5	6.5	8	V
Forward Current	I_F	$V_F = 4\text{V}$			0.1	μA
Reverse Current	I_R	$V_R = 4\text{V}$			0.1	μA

Absolute Maximum Rating (Ta=25°C)

Parameter	Symbol	Maximum Rating	Unit
Power dissipation	P_d	50	mW
Junction Temperature	T_j	150	°C

Description

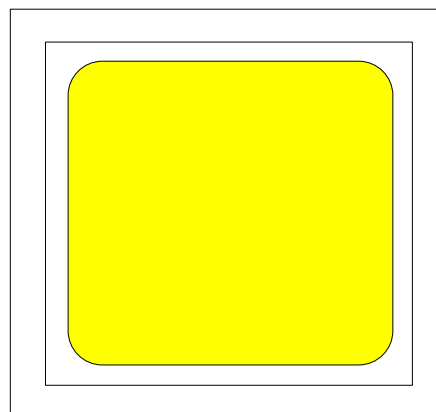
- PSZ-1021B-7V is silicon planar zener diode.
- $V_{Z(F)}$ means Zener voltage on forward bias.

Application

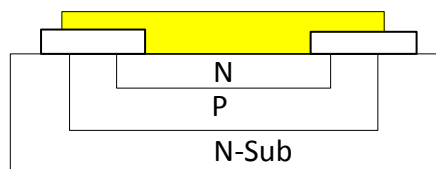
- ESD & Surge Protector for LEDs

Feature

- **Chip Size** : $190(\pm 20)\mu\text{m} \times 190(\pm 20)\mu\text{m}$
- **Chip Thickness** : $100\mu\text{m} \pm 15\mu\text{m}$
- **Structure** : Vertical N/P/N
- **Metallization**
 - Top(Anode) : Au
 - Bottom(Cathode) : Au
- **Bonding Pad Size**
 - Top(Anode) : $\square 150\mu\text{m}$

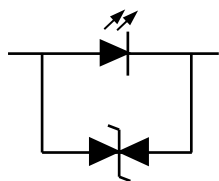


[Top View]



[Cross Section]

Schematic Diagram



Electrical and Optical Characteristics (Ta=25°C)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Forward Zener Voltage	$V_{Z(F)}$	$I_F = 5\text{mA}$	4.5	5.5	7	V
Reverse Zener Voltage	$V_{Z(R)}$	$I_Z = 5\text{mA}$	5	6.5	8	V
Forward Current	I_F	$V_F = 4\text{V}$			0.1	μA
Reverse Current	I_R	$V_R = 4\text{V}$			0.1	μA

Absolute Maximum Rating (Ta=25°C)

Parameter	Symbol	Maximum Rating	Unit
Power dissipation	P_d	50	mW
Junction Temperature	T_j	150	°C

Description

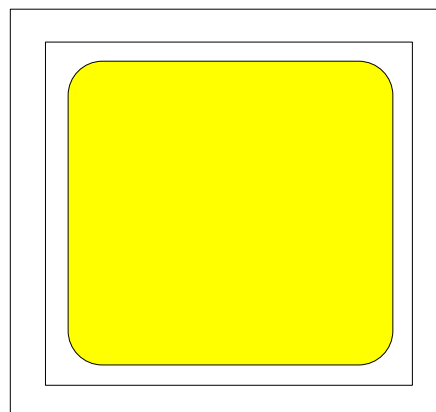
- PSZ-1023B-7V is silicon planar zener diode.
- $V_{Z(F)}$ means Zener voltage on forward bias.

Application

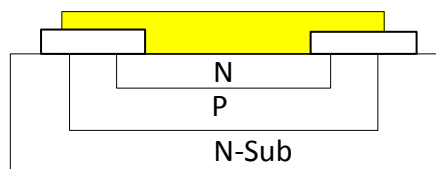
- ESD & Surge Protector for LEDs

Feature

- **Chip Size** : $210(\pm 20)\mu\text{m} \times 210(\pm 20)\mu\text{m}$
- **Chip Thickness** : $100\mu\text{m} \pm 15\mu\text{m}$
- **Structure** : Vertical N/P/N
- **Metallization**
 - Top(Anode) : Au
 - Bottom(Cathode) : Au
- **Bonding Pad Size**
 - Top(Anode) : $\square 160\mu\text{m}$

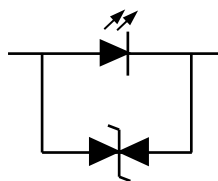


[Top View]



[Cross Section]

Schematic Diagram



Electrical and Optical Characteristics (Ta=25°C)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Forward Zener Voltage	$V_{Z(F)}$	$I_F = 5\text{mA}$	4.5	5.5	7	V
Reverse Zener Voltage	$V_{Z(R)}$	$I_Z = 5\text{mA}$	5	6.5	8	V
Forward Current	I_F	$V_F = 4\text{V}$			0.1	μA
Reverse Current	I_R	$V_R = 4\text{V}$			0.1	μA

Absolute Maximum Rating (Ta=25°C)

Parameter	Symbol	Maximum Rating	Unit
Power dissipation	P_d	100	mW
Junction Temperature	T_j	150	°C

Description

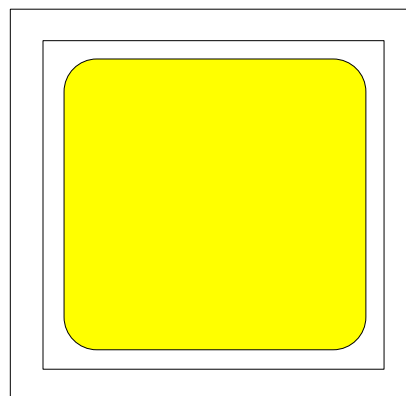
- PSZ-2021B-13V is silicon planar zener diode.
- $V_{Z(F)}$ means Zener voltage on forward bias.

Application

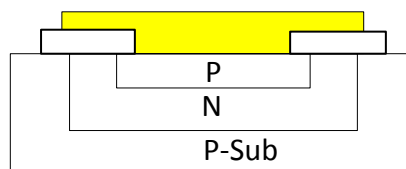
- ESD & Surge Protector for LEDs

Feature

- **Chip Size** : $190(\pm 20)\mu\text{m} \times 190(\pm 20)\mu\text{m}$
- **Chip Thickness** : $100\mu\text{m} \pm 15\mu\text{m}$
- **Structure** : Vertical P/N/P
- **Metallization**
 - Top(Cathode) : Au
 - Bottom(Anode) : Au
- **Bonding Pad Size**
 - Top(Cathode) : $\square 150\mu\text{m}$

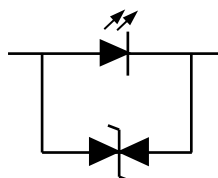


[Top View]



[Cross Section]

Schematic Diagram



Electrical and Optical Characteristics (Ta=25°C)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Forward Zener Voltage	$V_{Z(F)}$	$I_F = 5\text{mA}$	7	-	13	V
Reverse Zener Voltage	$V_{Z(R)}$	$I_Z = 5\text{mA}$	10	-	17	V
Forward Current	I_F	$V_F = 5\text{V}$	-	-	0.1	μA
Reverse Current	I_R	$V_R = 8\text{V}$	-	-	0.1	μA

Absolute Maximum Rating (Ta=25°C)

Parameter	Symbol	Maximum Rating	Unit
Power dissipation	P_d	50	mW
Junction Temperature	T_j	150	°C

Description

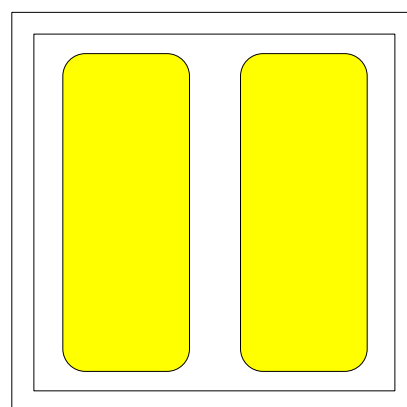
- PSZ-1034D-7V is silicon planar zener diode.
- Lateral P/N/P type. Isolated back side.

Application

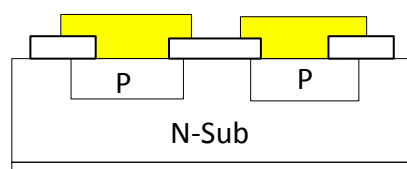
- ESD & Surge Protector for LEDs

Feature

- **Chip Size** : $320(\pm 20)\mu\text{m} \times 320(\pm 20)\mu\text{m}$
- **Chip Thickness** : $120\mu\text{m} \pm 15\mu\text{m}$
- **Structure** : Lateral P/N/P
- **Metallization**
 - Top(Anode) : Au
 - Bottom(Cathode) : Isolation (SiO_2)
- **Bonding Pad Size**
 - Top(Anode) : $\square 115\mu\text{m} \times 265\mu\text{m}$

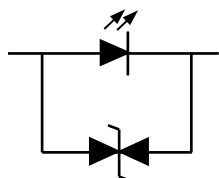


[Top View]



[Cross Section]

Schematic Diagram



Electrical and Optical Characteristics (Ta=25°C)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Forward Zener Voltage	$V_{Z(F)}$	$I_F = 5\text{mA}$	6	7.5	9	V
Reverse Zener Voltage	$V_{Z(R)}$	$I_Z = 5\text{mA}$	6	7.5	9	V
Forward Current	I_F	$V_F = 4\text{V}$			0.1	μA
Reverse Current	I_R	$V_R = 4\text{V}$			0.1	μA

Absolute Maximum Rating (Ta=25°C)

Parameter	Symbol	Maximum Rating	Unit
Power dissipation	P_d	50	mW
Junction Temperature	T_j	150	°C

Description

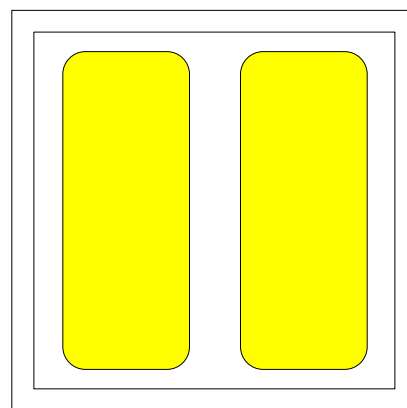
- PSZ-2034D-7V is silicon planar zener diode.
- Lateral N/P/N type. Isolated back side.

Application

- ESD & Surge Protector for LEDs

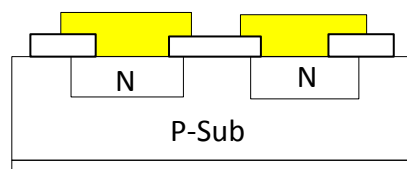
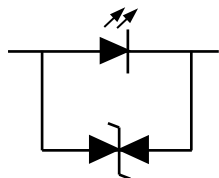
Feature

- **Chip Size** : $320(\pm 20)\mu\text{m} \times 320(\pm 20)\mu\text{m}$
- **Chip Thickness** : $120\mu\text{m} \pm 15\mu\text{m}$
- **Structure** : Lateral N/P/N
- **Metallization**
 - Top(Cathode) : Au
 - Bottom(Anode) : Isolation (SiO_2)
- **Bonding Pad Size**
 - Top(Cathode) : $\square 115\mu\text{m} \times 265\mu\text{m}$



[Top View]

Schematic Diagram



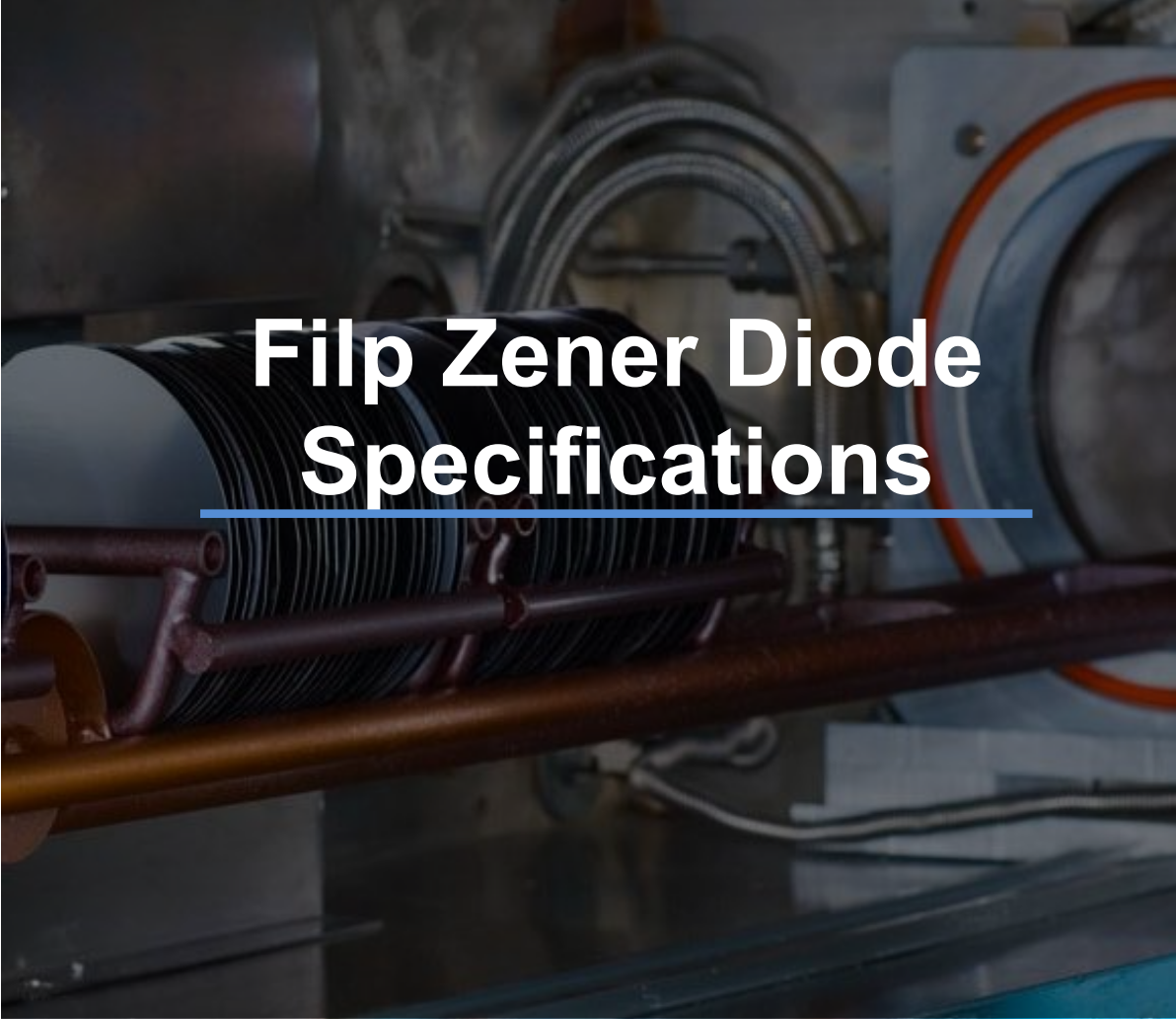
[Cross Section]

Electrical and Optical Characteristics (Ta=25°C)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Forward Zener Voltage	$V_{Z(F)}$	$I_F = 5\text{mA}$	6	7.5	9	V
Reverse Zener Voltage	$V_{Z(R)}$	$I_Z = 5\text{mA}$	6	7.5	9	V
Forward Current	I_F	$V_F = 4\text{V}$			0.1	μA
Reverse Current	I_R	$V_R = 4\text{V}$			0.1	μA

Absolute Maximum Rating (Ta=25°C)

Parameter	Symbol	Maximum Rating	Unit
Power dissipation	P_d	50	mW
Junction Temperature	T_j	150	°C



Filp Zener Diode Specifications

P&L SEMI
Power and Lighting Semiconductor

www.pnlsemi.com
+82-63-714-3737
smgoh@pnlsemi.com

Description

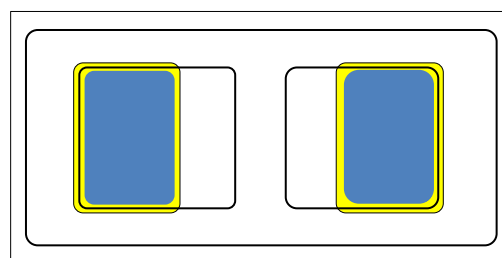
- PSZ-1044023F-8V is silicon planar Zener Diode for Flip Bonding.
- Lateral P/N/P type.

Application

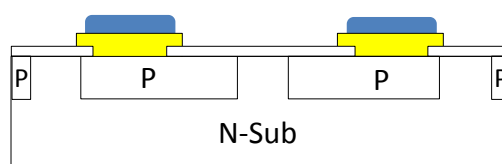
- ESD & Surge Protector for LEDs

Feature

- **Chip Size** : $420(\pm 20)\mu\text{m} \times 210(\pm 20)\mu\text{m}$
- **Chip Thickness** : $100\mu\text{m} \pm 15\mu\text{m}$
- **Structure** : Lateral P/N/P
- **Metallization**
 - > **Top**
 - Diffusion Barrier : Gold(Au)
 - Solder : Gold-Tin(Au/Sn) 3um
 - > **Bottom** : None
- **Bonding Pad Size**
 - Diffusion Barrier : □ $90\mu\text{m} \times 120\mu\text{m}$
 - Solder : □ $70\mu\text{m} \times 100\mu\text{m}$
 - Distance of Pad to Pad : $130\mu\text{m}$



[Top View]



[Cross Section]

Electrical and Optical Characteristics (Ta=25°C)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Forward Zener Voltage	$V_{Z(F)}$	$I_F = 5\text{mA}$	7	8	10	V
Reverse Zener Voltage	$V_{Z(R)}$	$I_Z = 5\text{mA}$	7	8	10	V
Forward Current	I_F	$V_F = 4\text{V}$			0.1	μA
Reverse Current	I_R	$V_R = 4\text{V}$			0.1	μA

Absolute Maximum Rating (Ta=25°C)

Parameter	Symbol	Maximum Rating	Unit
Power dissipation	P_d	50	mW
Junction Temperature	T_j	150	°C

Description

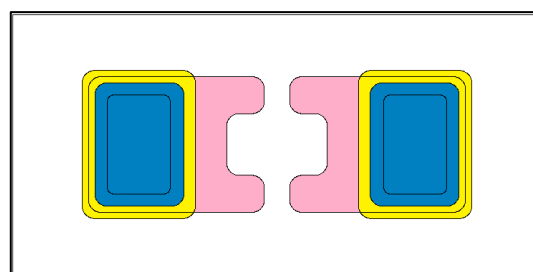
- PSZ-1044023FA-8V is silicon planar Zener Diode for Flip Bonding.
- Lateral P/N/P type.

Application

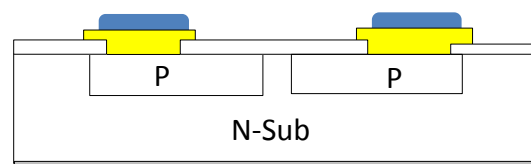
- ESD & Surge Protector for LEDs

Feature

- **Chip Size** : $420(\pm 20)\mu\text{m} \times 210(\pm 20)\mu\text{m}$
- **Chip Thickness** : $100\mu\text{m} \pm 15\mu\text{m}$
- **Structure** : Lateral P/N/P
- **Metallization**
 - > **Top**
 - Diffusion Barrier : Gold(Au)
 - Solder : Gold-Tin(Au/Sn) 3um
 - > **Bottom** : Al
- **Bonding Pad Size**
 - Diffusion Barrier : $\square 90\mu\text{m} \times 120\mu\text{m}$
 - Solder : $\square 70\mu\text{m} \times 100\mu\text{m}$
 - Distance of Pad to Pad : $130\mu\text{m}$



[Top View]



[Cross Section]

Electrical and Optical Characteristics (Ta=25°C)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Forward Zener Voltage	$V_{Z(F)}$	$I_F = 5\text{mA}$	7	8	10	V
Reverse Zener Voltage	$V_{Z(R)}$	$I_Z = 5\text{mA}$	7	8	10	V
Forward Current	I_F	$V_F = 4\text{V}$			0.1	μA
Reverse Current	I_R	$V_R = 4\text{V}$			0.1	μA

Absolute Maximum Rating (Ta=25°C)

Parameter	Symbol	Maximum Rating	Unit
Power dissipation	P_d	50	mW
Junction Temperature	T_j	150	°C

Description

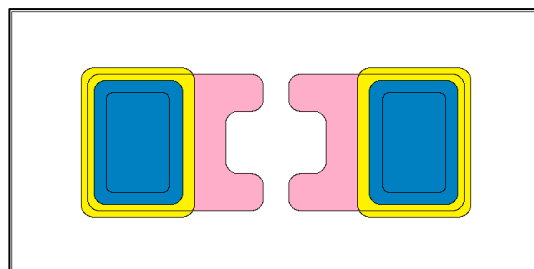
- PSZ-1044023F-20V is silicon planar Zener Diode for Flip Bonding.
- Lateral P/N/P type.

Application

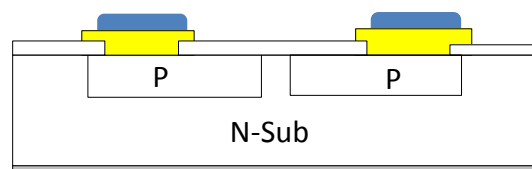
- ESD & Surge Protector for LEDs

Feature

- **Chip Size** : $420(\pm 20)\mu\text{m} \times 210(\pm 20)\mu\text{m}$
- **Chip Thickness** : $100\mu\text{m} \pm 15\mu\text{m}$
- **Structure** : Lateral P/N/P
- **Metallization**
 - > **Top**
 - Diffusion Barrier : Gold(Au)
 - Solder : Gold-Tin(Au/Sn) 3um
 - > **Bottom** : Al
- **Bonding Pad Size**
 - Diffusion Barrier : $\square 90\mu\text{m} \times 120\mu\text{m}$
 - Solder : $\square 70\mu\text{m} \times 100\mu\text{m}$
 - Distance of Pad to Pad : $130\mu\text{m}$



[Top View]



[Cross Section]

Electrical and Optical Characteristics (Ta=25°C)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Forward Zener Voltage	$V_{Z(F)}$	$I_F = 5\text{mA}$	16	20	24	V
Reverse Zener Voltage	$V_{Z(R)}$	$I_Z = 5\text{mA}$	16	20	24	V
Forward Current	I_F	$V_F = 14\text{V}$			0.1	μA
Reverse Current	I_R	$V_R = 14\text{V}$			0.1	μA

Absolute Maximum Rating (Ta=25°C)

Parameter	Symbol	Maximum Rating	Unit
Power dissipation	P_d	50	mW
Junction Temperature	T_j	150	°C

Description

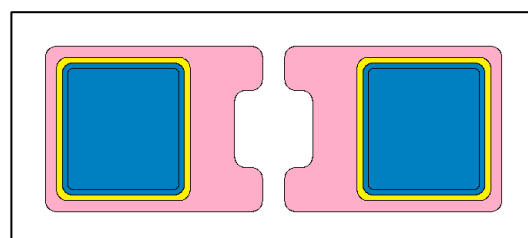
- PSZ-1049023F-8V is silicon planar Zener Diode for Flip Bonding.
- Lateral P/N/P type.

Application

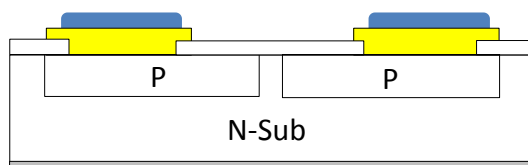
- ESD & Surge Protector for LEDs

Feature

- **Chip Size** : $470(\pm 20)\mu\text{m} \times 210(\pm 20)\mu\text{m}$
- **Chip Thickness** : $100\mu\text{m} \pm 15\mu\text{m}$
- **Structure** : Lateral P/N/P
- **Metallization**
 - > **Top**
 - Diffusion Barrier : Gold(Au)
 - Solder : Gold-Tin(Au/Sn) 3um
 - > **Bottom** : Al
- **Bonding Pad Size**
 - Diffusion Barrier : □ $120\mu\text{m} \times 130\mu\text{m}$
 - Solder : □ $100\mu\text{m} \times 110\mu\text{m}$
 - Distance of Pad to Pad : $150\mu\text{m}$



[Top View]



[Cross Section]

Electrical and Optical Characteristics (Ta=25°C)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Forward Zener Voltage	$V_{Z(F)}$	$I_F = 5\text{mA}$	7	8	10	V
Reverse Zener Voltage	$V_{Z(R)}$	$I_Z = 5\text{mA}$	7	8	10	V
Forward Current	I_F	$V_F = 4\text{V}$			0.1	μA
Reverse Current	I_R	$V_R = 4\text{V}$			0.1	μA

Absolute Maximum Rating (Ta=25°C)

Parameter	Symbol	Maximum Rating	Unit
Power dissipation	P_d	50	mW
Junction Temperature	T_j	150	°C

Description

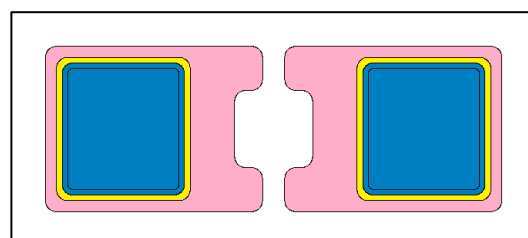
- PSZ-1049023F-20V is silicon planar Zener Diode for Flip Bonding.
- Lateral P/N/P type.

Application

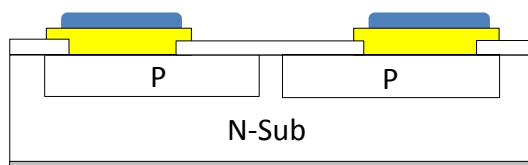
- ESD & Surge Protector for LEDs

Feature

- **Chip Size** : $470(\pm 20)\mu\text{m} \times 210(\pm 20)\mu\text{m}$
- **Chip Thickness** : $100\mu\text{m} \pm 15\mu\text{m}$
- **Structure** : Lateral P/N/P
- **Metallization**
 - > **Top**
 - Diffusion Barrier : Gold(Au)
 - Solder : Gold-Tin(Au/Sn) 3um
 - > **Bottom** : Al
- **Bonding Pad Size**
 - Diffusion Barrier : □ $120\mu\text{m} \times 130\mu\text{m}$
 - Solder : □ $100\mu\text{m} \times 110\mu\text{m}$
 - Distance of Pad to Pad : $150\mu\text{m}$



[Top View]



[Cross Section]

Electrical and Optical Characteristics (Ta=25°C)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Forward Zener Voltage	$V_{Z(F)}$	$I_F = 5\text{mA}$	16	20	24	V
Reverse Zener Voltage	$V_{Z(R)}$	$I_Z = 5\text{mA}$	16	20	24	V
Forward Current	I_F	$V_F = 14\text{V}$			0.1	μA
Reverse Current	I_R	$V_R = 14\text{V}$			0.1	μA

Absolute Maximum Rating (Ta=25°C)

Parameter	Symbol	Maximum Rating	Unit
Power dissipation	P_d	50	mW
Junction Temperature	T_j	150	°C

Description

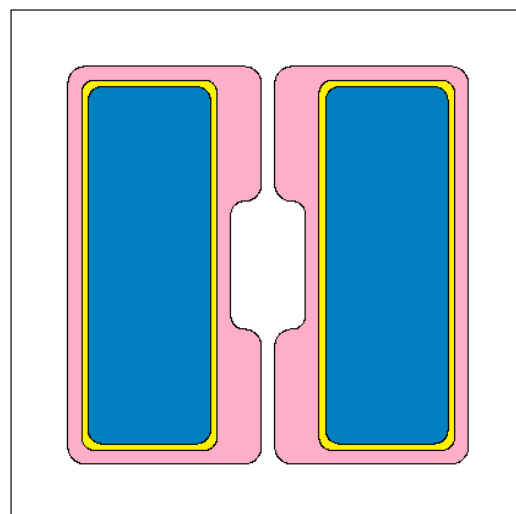
- PSZ-1039039F-8V5 is silicon planar Zener Diode for Flip Bonding.
- Lateral P/N/P type.

Application

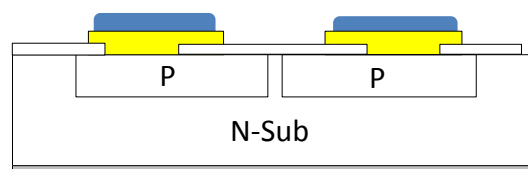
- ESD & Surge Protector for LEDs

Feature

- **Chip Size** : $375(\pm 20)\mu\text{m} \times 375(\pm 20)\mu\text{m}$
- **Chip Thickness** : $150\mu\text{m} \pm 15\mu\text{m}$
- **Structure** : Lateral P/N/P
- **Metallization**
 - > **Top**
 - Diffusion Barrier : Gold(Au)
 - Solder : Gold-Tin(Au/Sn) 3um
 - > **Bottom** : Al
- **Bonding Pad Size**
 - Diffusion Barrier : $\square 100\mu\text{m} \times 275\mu\text{m}$
 - Solder : $\square 90\mu\text{m} \times 265\mu\text{m}$
 - Distance of Pad to Pad : $85\mu\text{m}$



[Top View]



[Cross Section]

Electrical and Optical Characteristics (Ta=25°C)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Forward Zener Voltage	$V_{Z(F)}$	$I_F = 5\text{mA}$	7	8	10	V
Reverse Zener Voltage	$V_{Z(R)}$	$I_Z = 5\text{mA}$	7	8	10	V
Forward Current	I_F	$V_F = 4\text{V}$			0.1	μA
Reverse Current	I_R	$V_R = 4\text{V}$			0.1	μA

Absolute Maximum Rating (Ta=25°C)

Parameter	Symbol	Maximum Rating	Unit
Power dissipation	P_d	100	mW
Junction Temperature	T_j	150	°C

Description

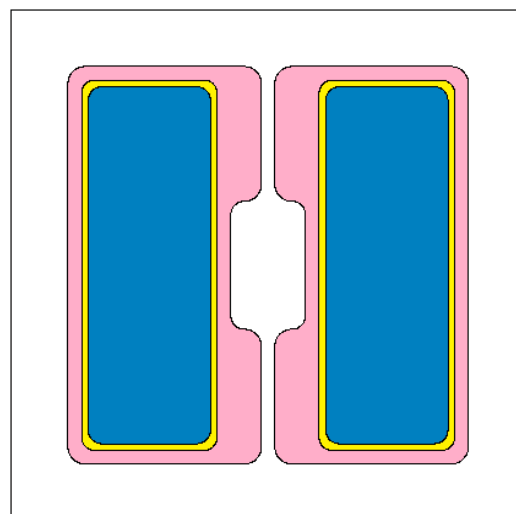
- PSZ-1039039F-20V5 is silicon planar Zener Diode for Flip Bonding.
- Lateral P/N/P type.

Application

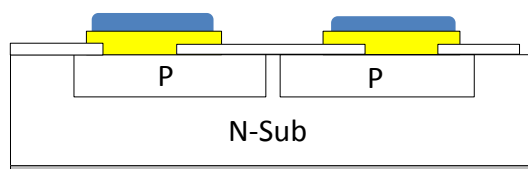
- ESD & Surge Protector for LEDs

Feature

- **Chip Size** : $375(\pm 20)\mu\text{m} \times 375(\pm 20)\mu\text{m}$
- **Chip Thickness** : $150\mu\text{m} \pm 15\mu\text{m}$
- **Structure** : Lateral P/N/P
- **Metallization**
 - > **Top**
 - Diffusion Barrier : Gold(Au)
 - Solder : Gold-Tin(Au/Sn) 3um
 - > **Bottom** : Al
- **Bonding Pad Size**
 - Diffusion Barrier : $\square 100\mu\text{m} \times 275\mu\text{m}$
 - Solder : $\square 90\mu\text{m} \times 265\mu\text{m}$
 - Distance of Pad to Pad : $85\mu\text{m}$



[Top View]



[Cross Section]

Electrical and Optical Characteristics (Ta=25°C)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Forward Zener Voltage	$V_{Z(F)}$	$I_F = 5\text{mA}$	16	20	24	V
Reverse Zener Voltage	$V_{Z(R)}$	$I_Z = 5\text{mA}$	16	20	24	V
Forward Current	I_F	$V_F = 14\text{V}$			0.1	μA
Reverse Current	I_R	$V_R = 14\text{V}$			0.1	μA

Absolute Maximum Rating (Ta=25°C)

Parameter	Symbol	Maximum Rating	Unit
Power dissipation	P_d	100	mW
Junction Temperature	T_j	150	°C

Description

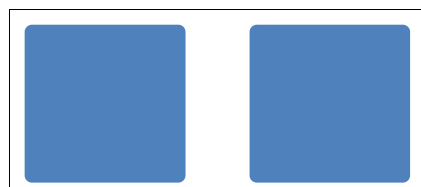
- PSZ-1056026F-20V is silicon planar Zener Diode for Flip Bonding.
- Lateral P/N/P type.

Application

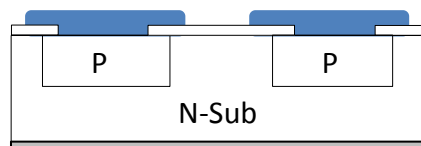
- ESD & Surge Protector for LEDs

Feature

- **Chip Size** : $540(\pm 20)\mu\text{m} \times 240(\pm 20)\mu\text{m}$
- **Chip Thickness** : $100\mu\text{m} \pm 15\mu\text{m}$
- **Structure** : Lateral P/N/P
- **Metallization**
 - > **Top**
 - Diffusion Barrier : Gold(Au)
 - Solder : Gold-Tin(Au/Sn) 3um
 - > **Bottom** : Al
- **Bonding Pad Size**
 - Diffusion Barrier : $\square 220\mu\text{m} \times 220\mu\text{m}$
 - Solder : $\square 200\mu\text{m} \times 200\mu\text{m}$
 - Distance of Pad to Pad : $150\mu\text{m}$



[Top View]



[Cross Section]

Electrical and Optical Characteristics (Ta=25°C)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Forward Zener Voltage	$V_{Z(F)}$	$I_F = 5\text{mA}$	16	20	24	V
Reverse Zener Voltage	$V_{Z(R)}$	$I_Z = 5\text{mA}$	16	20	24	V
Forward Current	I_F	$V_F = 14\text{V}$			0.1	μA
Reverse Current	I_R	$V_R = 14\text{V}$			0.1	μA

Absolute Maximum Rating (Ta=25°C)

Parameter	Symbol	Maximum Rating	Unit
Power dissipation	P_d	50	mW
Junction Temperature	T_j	150	°C

Custom Solutions

P&L Semi designs and manufactures customized silicon devices. Based on our experienced R&D systems, P&L Semi will specify, design and manufacture a device for your application.

Custom Device Manufacture Process

